



*Handwritten signature and date 12/5/02*

*(PRIVATE ART)*

FIG. 1A

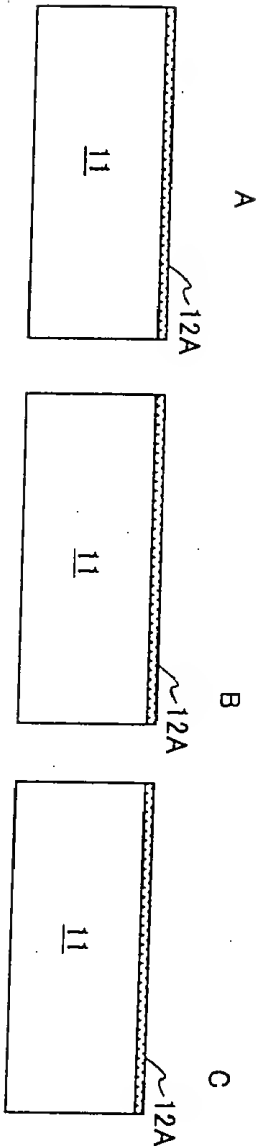


FIG. 1B

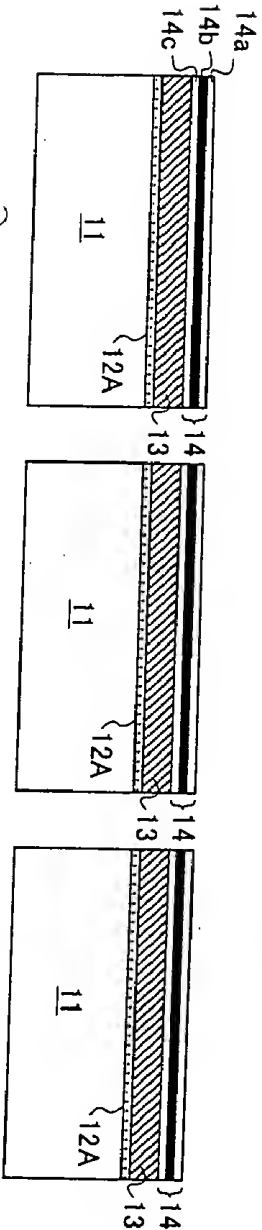


FIG. 1C

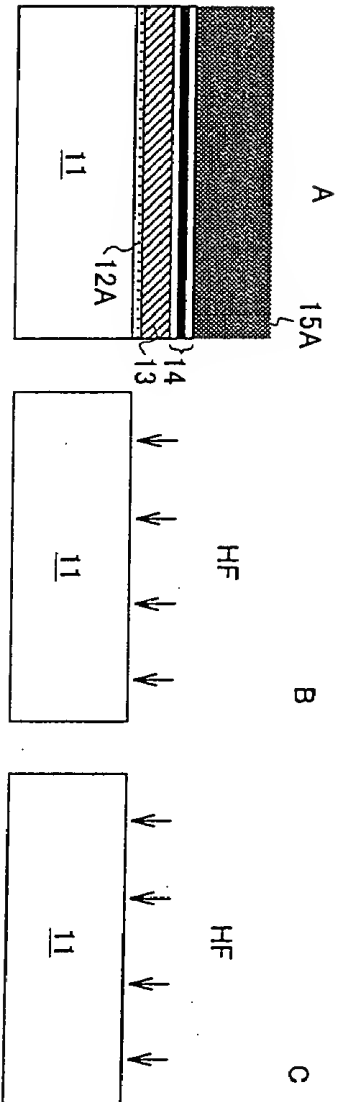
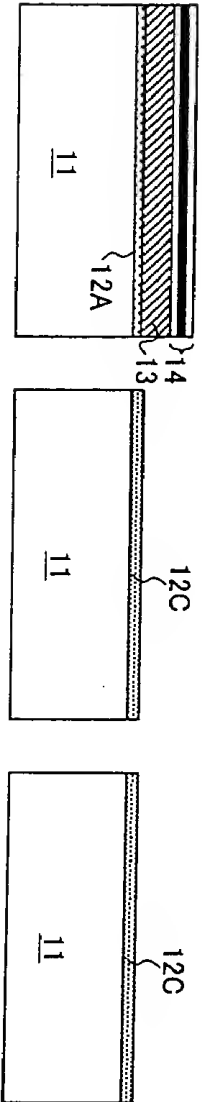


FIG. 1D



*Hydrogen  
insulator*

(Prior Art)



FIG. 1E

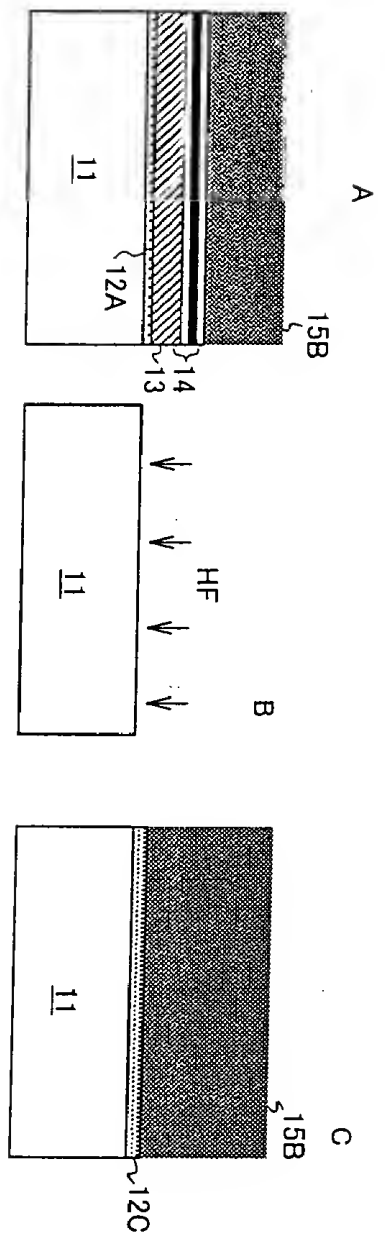
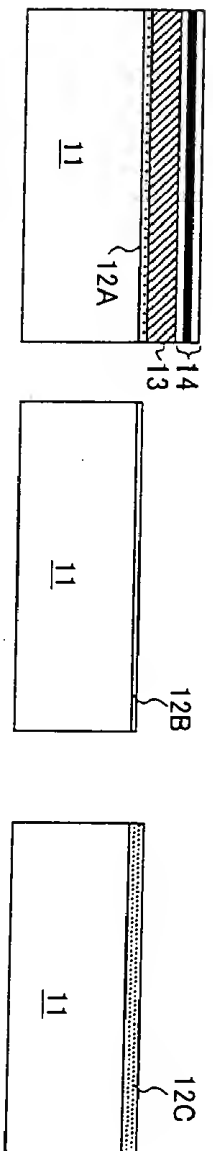


FIG. 1F



*Approved*  
*12/5/02*

(PRIOR ART)

FIG. 1G

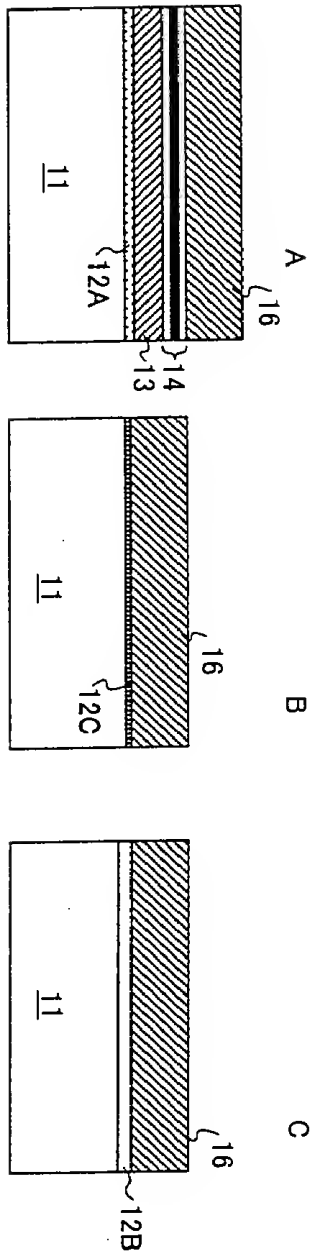
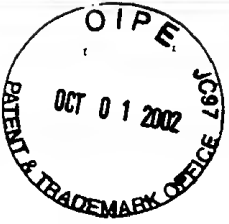
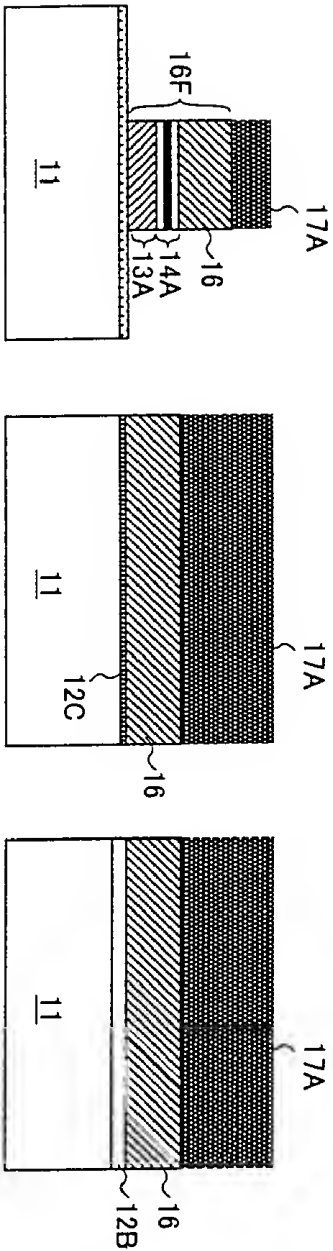


FIG. 1H



*Approved*  
12/5/02

(PRIOR ART)



*Hyman D. [Signature]*  
12/5/02

(PRIOR ART)

FIG. 1I

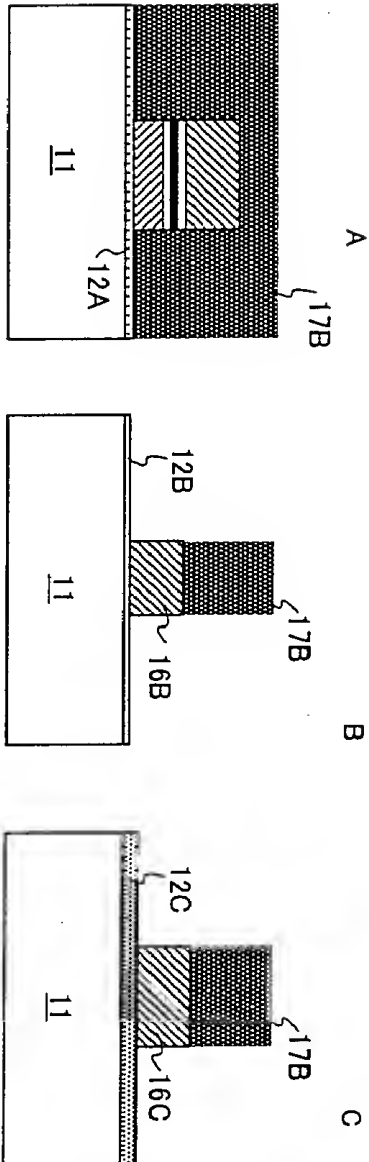
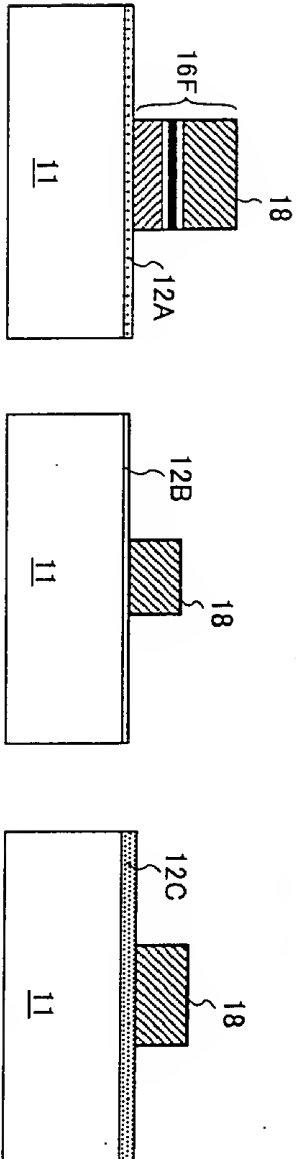


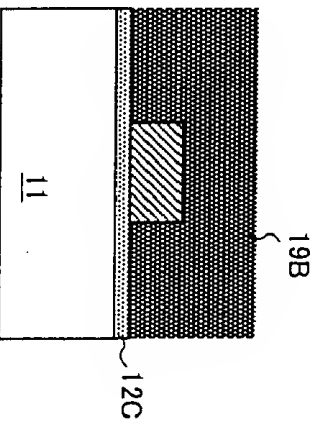
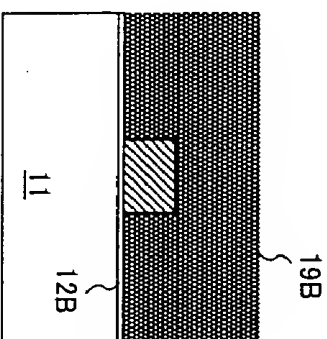
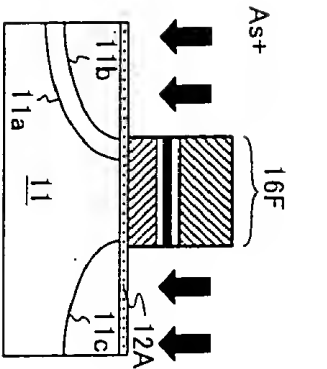
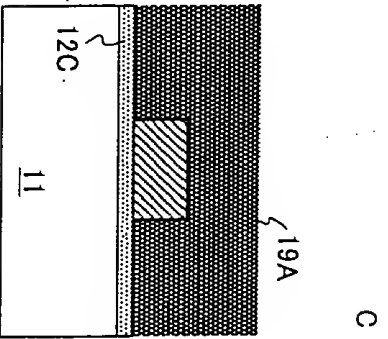
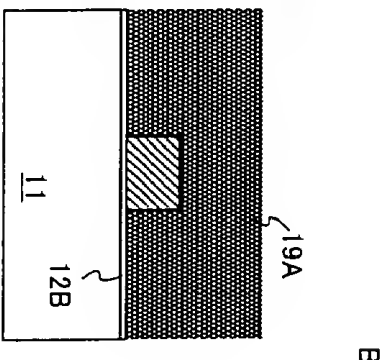
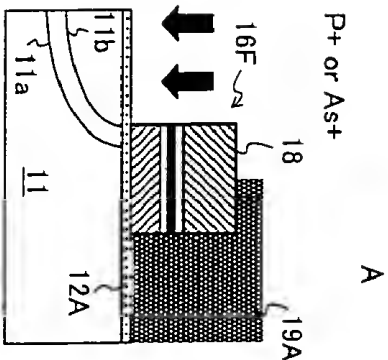
FIG. 1J





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11/5/02

(PRIOR ART)



A

B

C

FIG. 1M

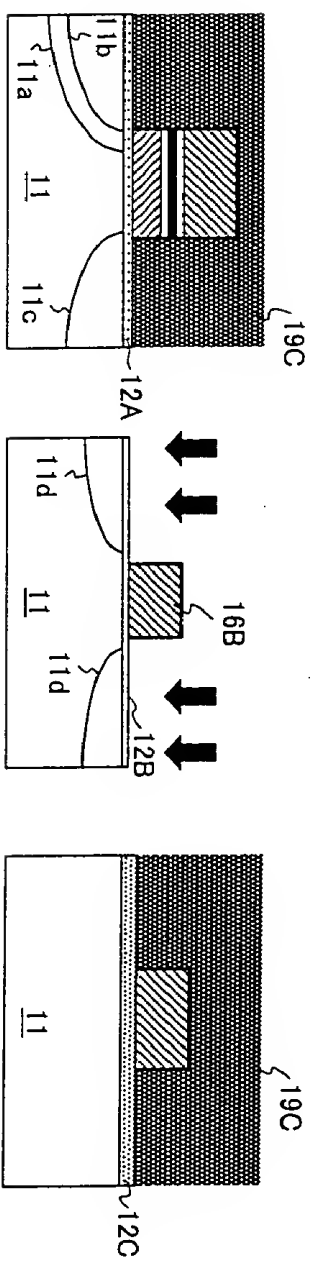
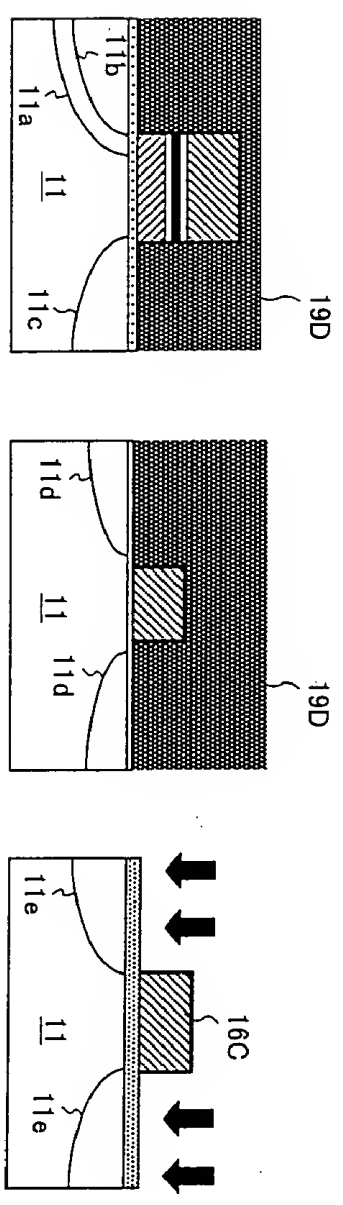


FIG. 1N



O.I.P.E.  
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*Handwritten signature and initials*

(PRIOR ART)



*Hyman*  
11/5/02

(Prior Art)

FIG. 10

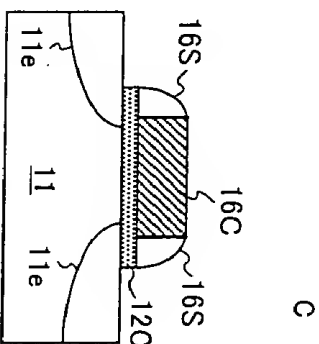
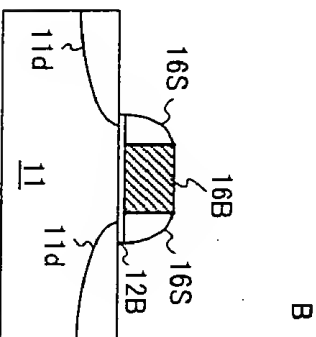
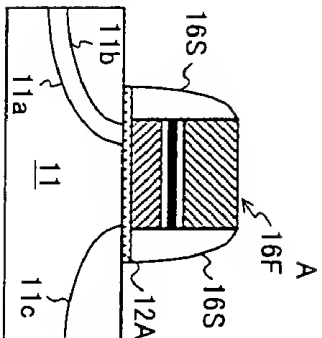
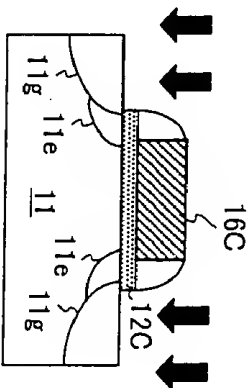
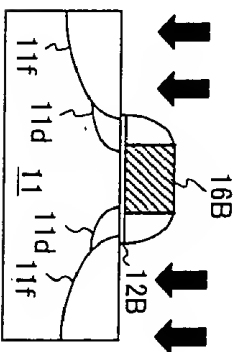
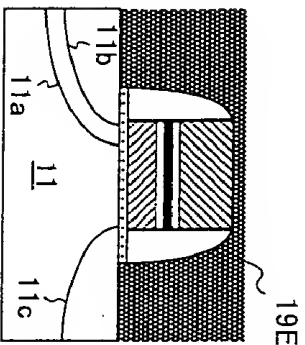


FIG. 1P



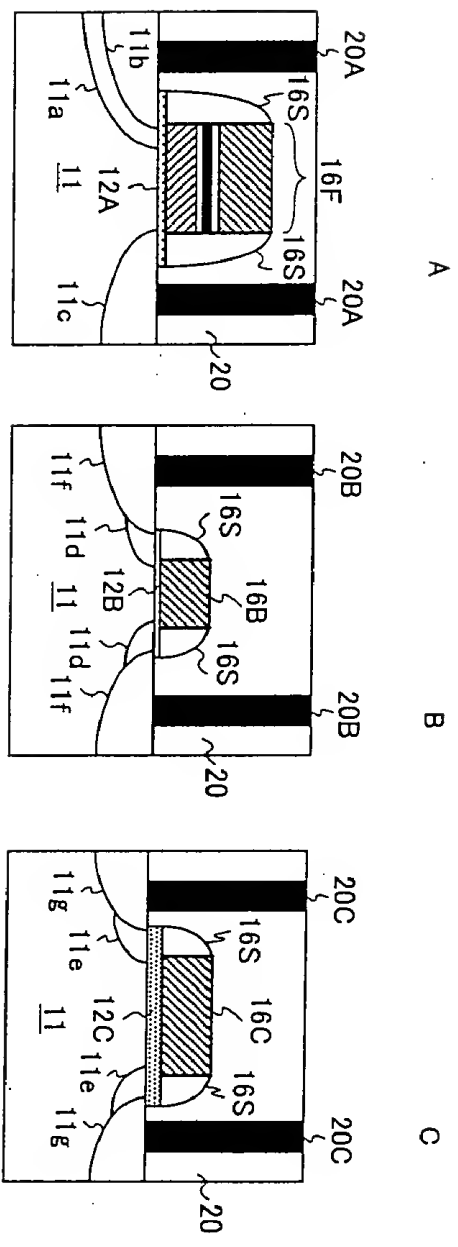




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*(PRIOR ART)*

FIG. 10





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FIG. 2A

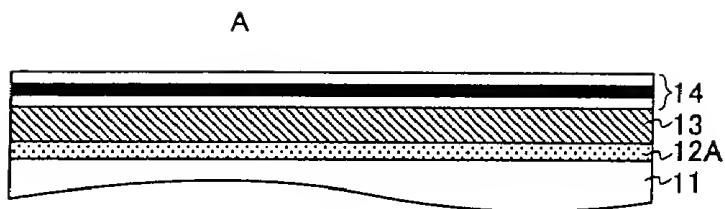


FIG. 2B

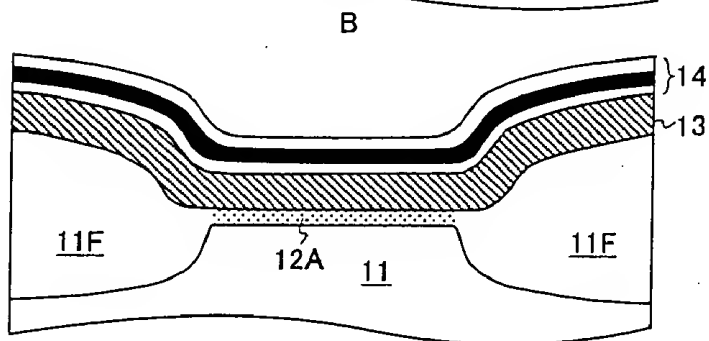
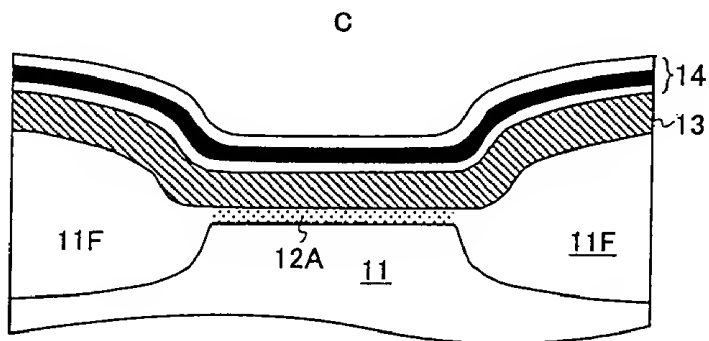


FIG. 2C



(PRIOR ART)



FIG. 3A

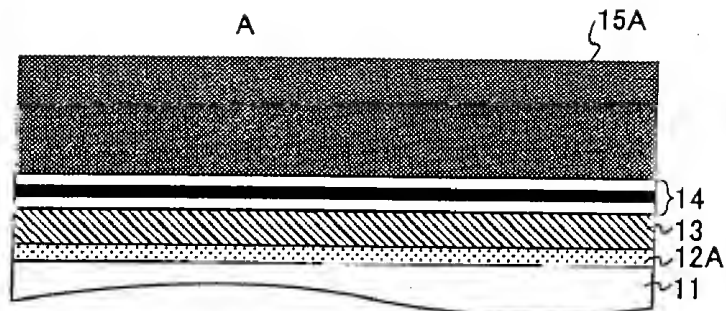


FIG. 3B

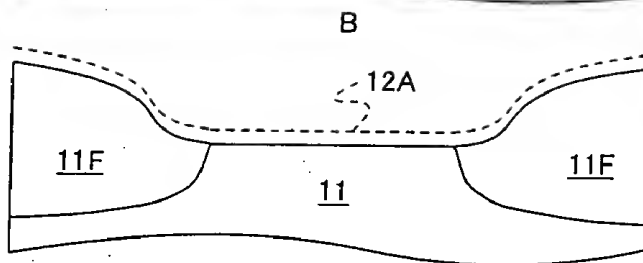
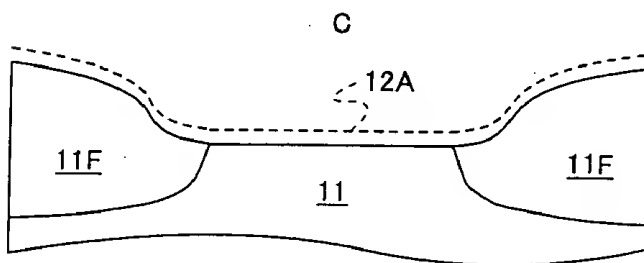


FIG. 3C



Approved  
10/5/02

(RELATED ART)



FIG. 4A

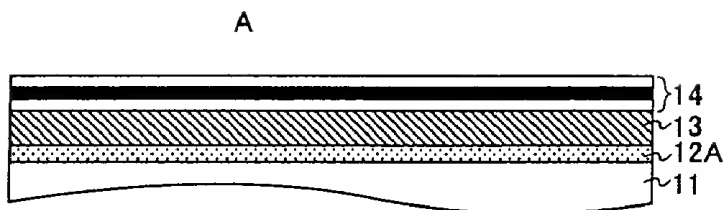


FIG. 4B

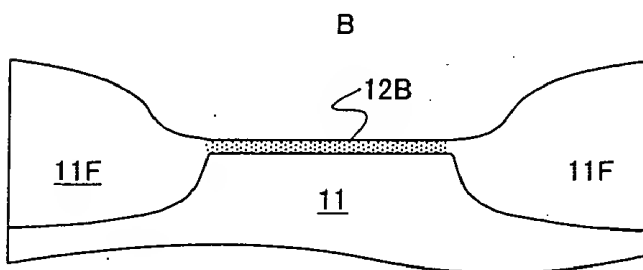
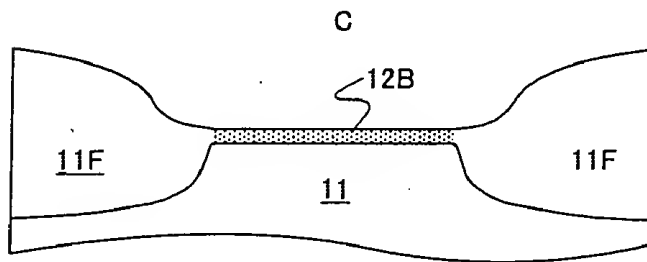


FIG. 4C



*Approved*  
12/5/02

(RELATED ART)



FIG. 5A

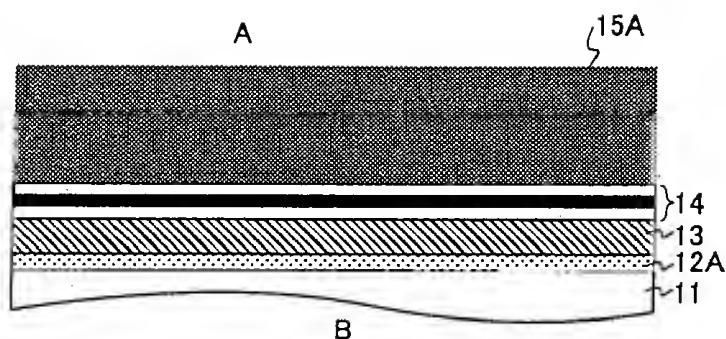


FIG. 5B

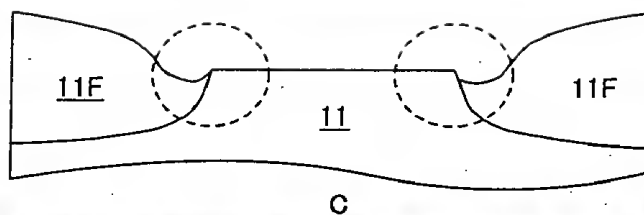
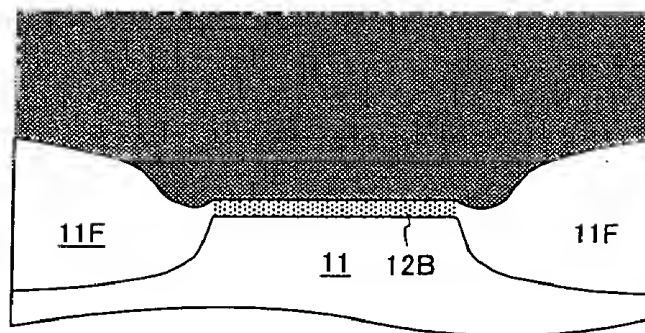


FIG. 5C



*Approved*  
12/5/02

(RELATED ART)



FIG. 6A

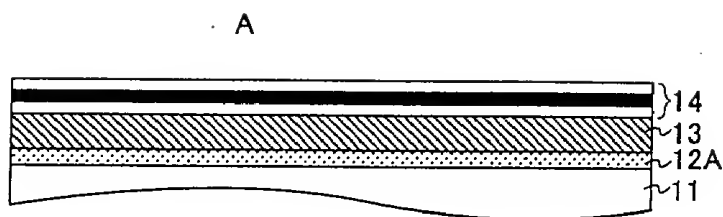


FIG. 6B

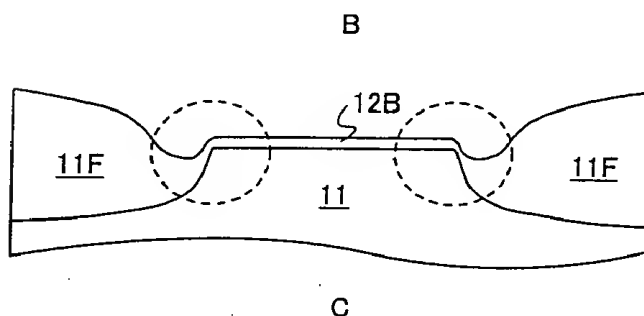
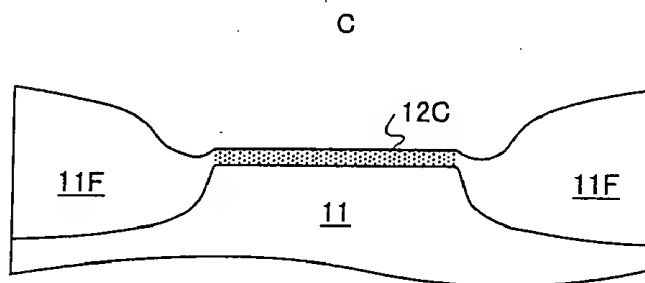


FIG. 6C



Approved  
12/5/02

(RELATED ART)



FIG. 7A

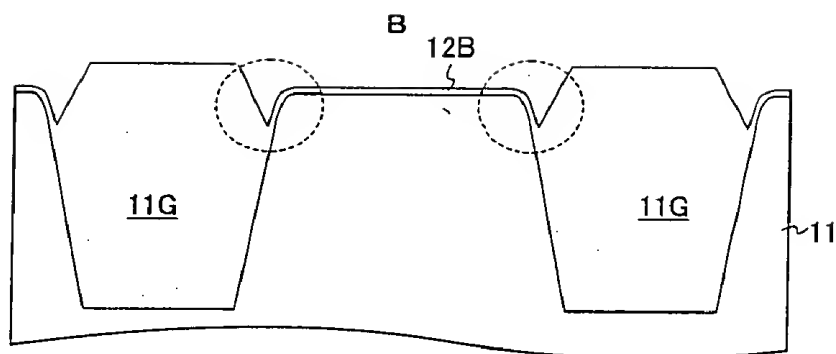
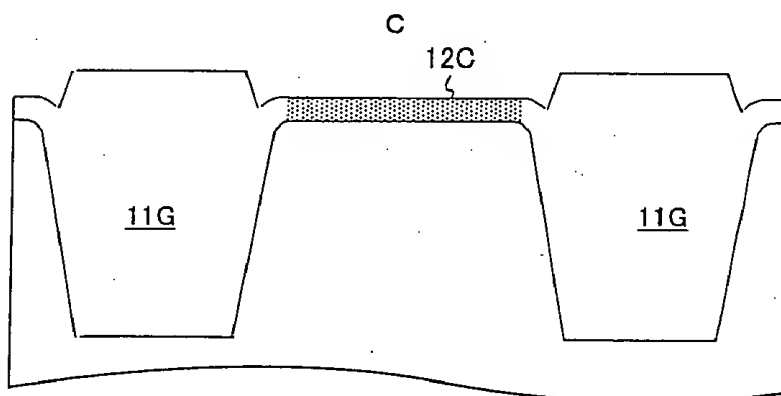


FIG. 7B



(RELATED ART)

Approved: [Signature]  
12/5/02

FIG. 8A

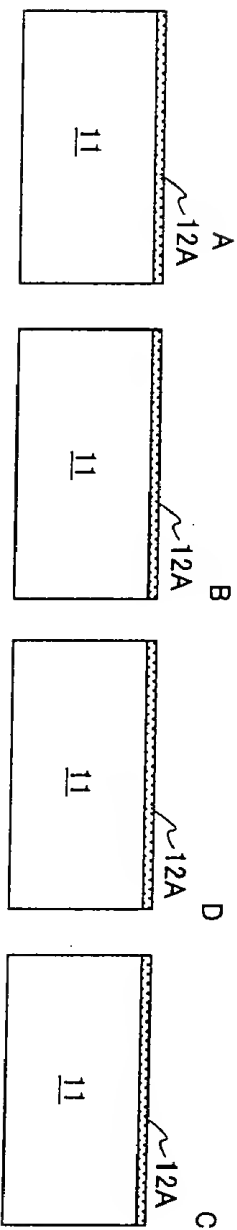
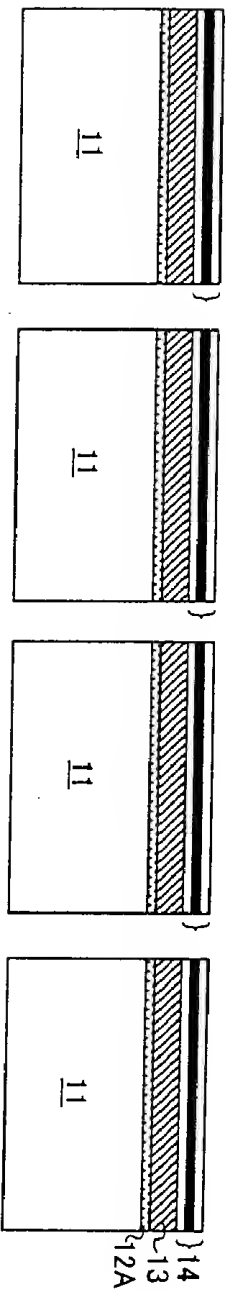


FIG. 8B



(PRIOR ART)

Approved 11/5/02





Figure 1 illustrates the cross-sectional views of a semiconductor device in three stages: A, B, and D.

- Stage A:** A substrate 11 is shown with a stack of layers. Layer 12A is the bottom layer, followed by layer 13, layer 14, and layer 15A on top. A bracket indicates that layers 12A, 13, and 14 are collectively referred to as 12.
- Stage B:** The device is shown after the removal of layer 15A. The etching process is labeled "HF" (hydrofluoric acid). Arrows indicate the direction of etching from the top surface.
- Stage D:** The device is shown after the removal of layer 14. The etching process is labeled "HF". Arrows indicate the direction of etching from the top surface.

Figure 1 shows four cross-sectional views of a semiconductor device, labeled (a), (b), (c), and (d). Each view shows a substrate 11 with a thin layer 12 on its top surface.

- (a) The thin layer 12 is a single layer with a hatched pattern. It is labeled 12A. A bracket indicates its thickness is 12C.
- (b) The thin layer 12 is a single layer with a dotted pattern. It is labeled 12B. A bracket indicates its thickness is 12C.
- (c) The thin layer 12 is a single layer with a dotted pattern. It is labeled 12C. A bracket indicates its thickness is 12C.
- (d) The thin layer 12 is a single layer with a dotted pattern. It is labeled 12C. A bracket indicates its thickness is 12C.



PRIOR ACT

Approved/et  
P/S/er



FIG. 8E

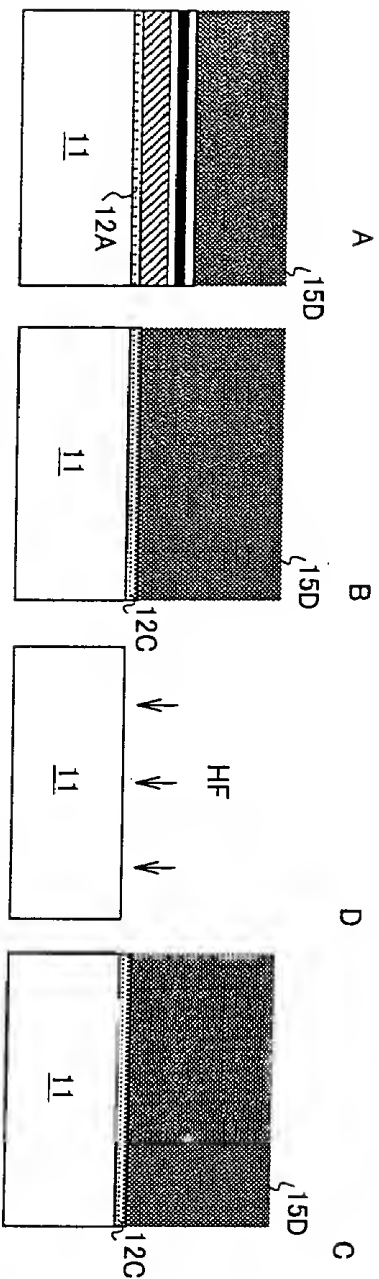
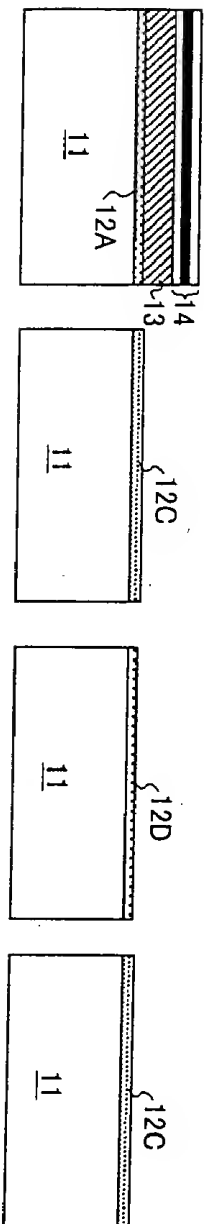


FIG. 8F



Prior Art

12/5/02

FIG. 8G

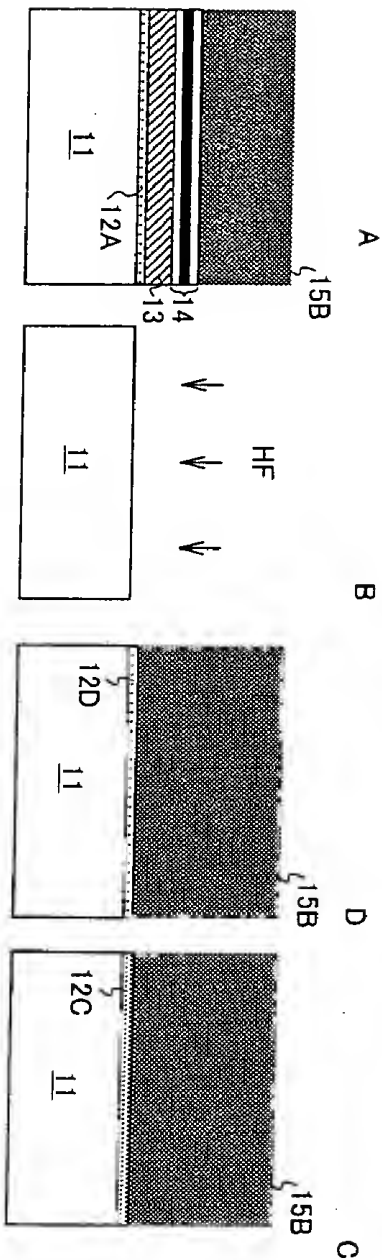
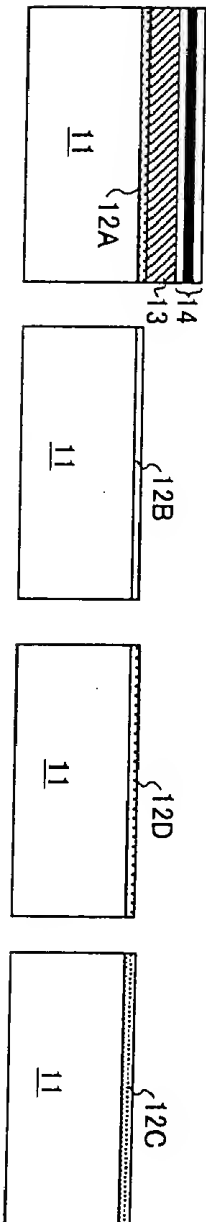


FIG. 8H



(PRIOR ART) *Handwritten signature*  
12/5/02

A

B

D

C

FIG. 8I

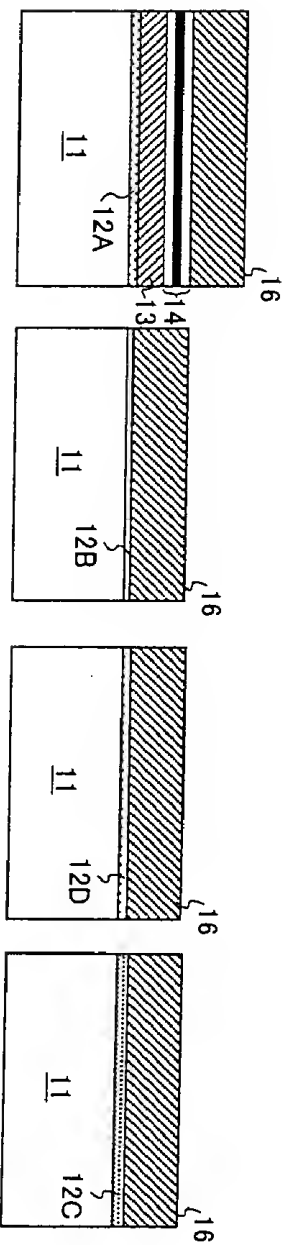
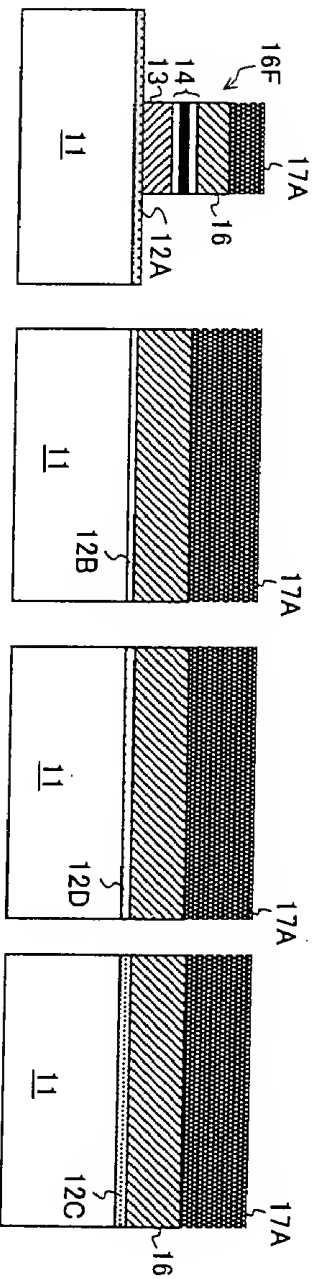


FIG. 8J



(Prior Art)

Approved 12/5/02



FIG. 8K

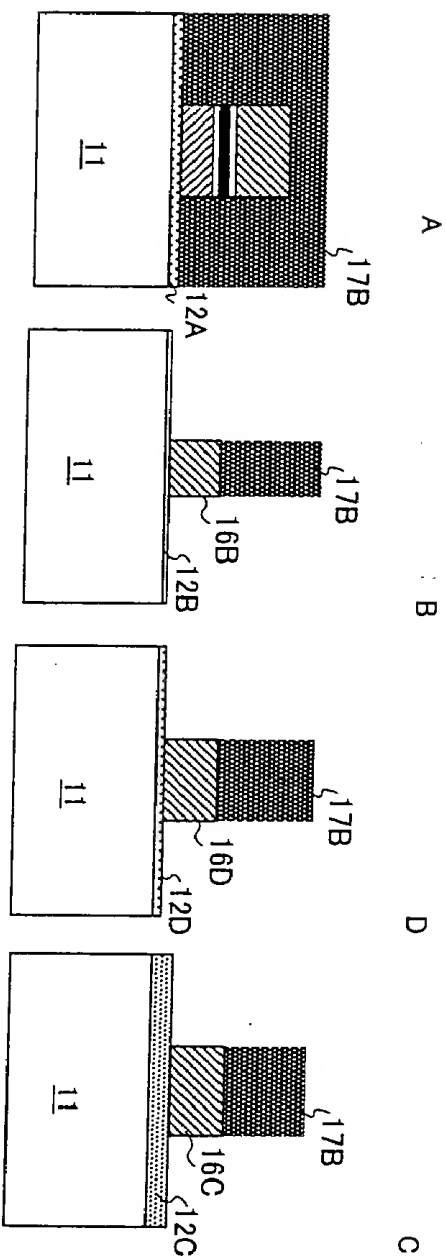
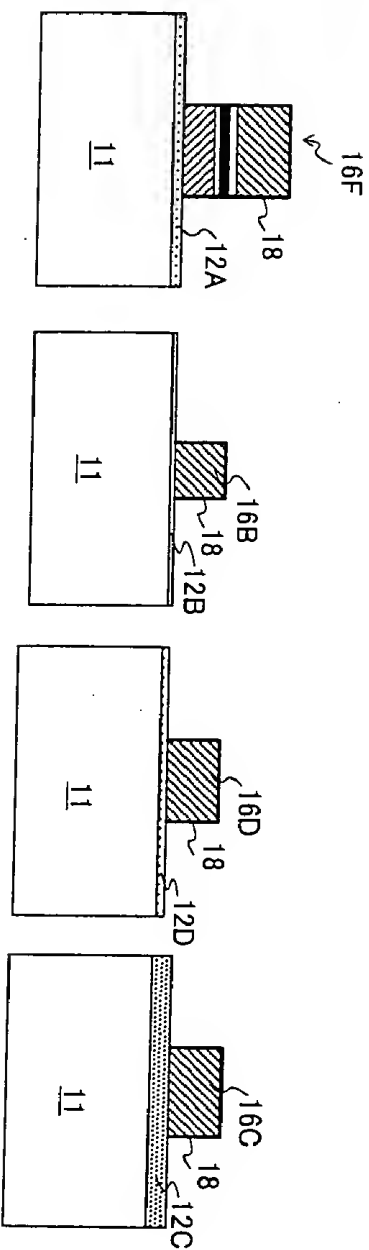


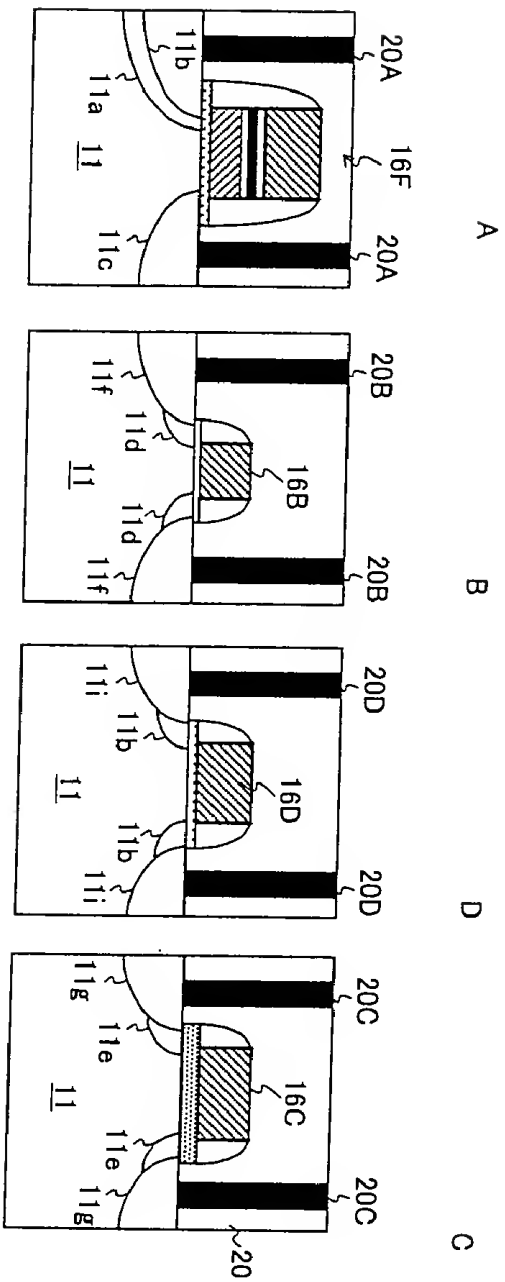
FIG. 8L



(Prior Art)

Approved *[Signature]*  
v/s/22

FIG. 8M



(PRIOR ART)

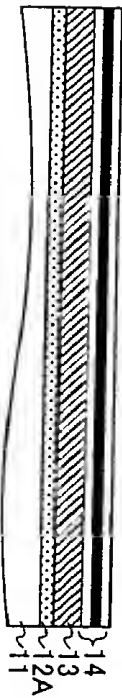
Approved 12/5/02

*[Signature]*



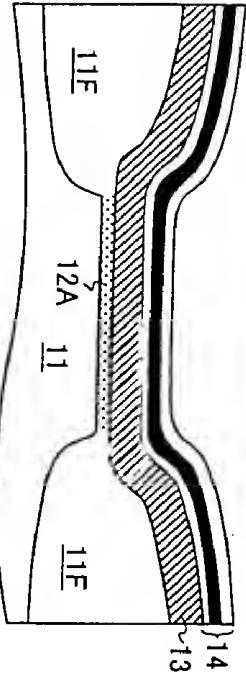


FIG. 9A



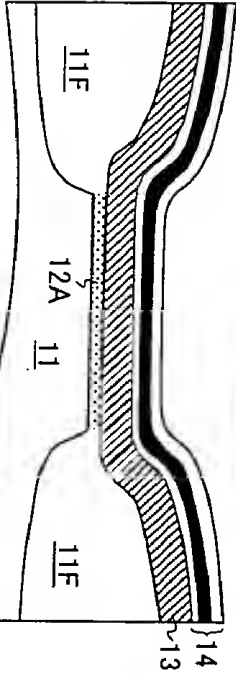
A

FIG. 9B



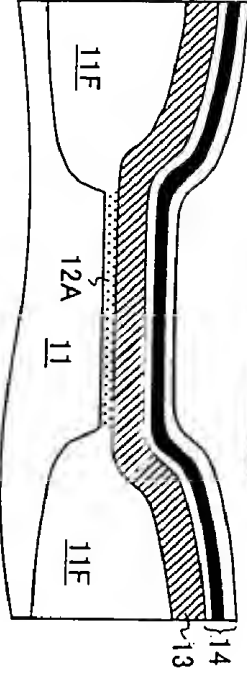
B

FIG. 9C



D

FIG. 9D



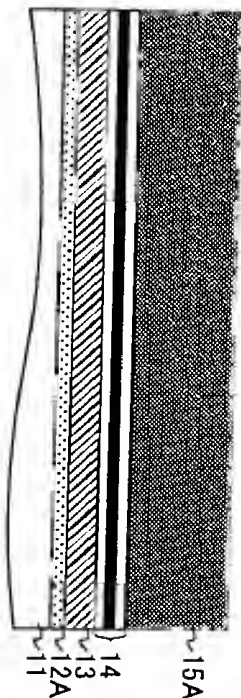
C

(RELATED ART)

April 12/5/02  
[Signature]

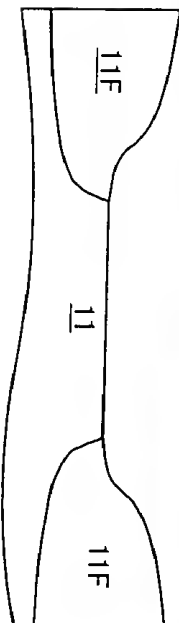


FIG. 10A



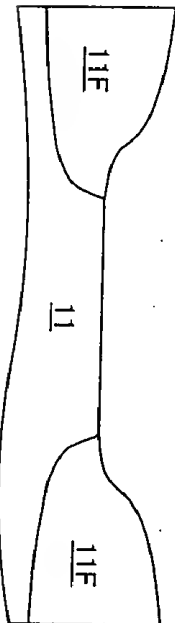
A

FIG. 10B



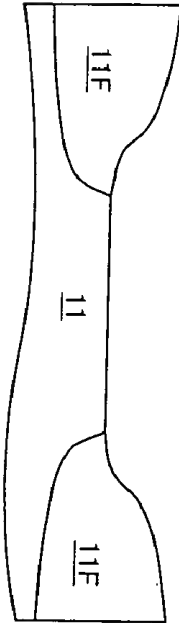
B

FIG. 10C



D

FIG. 10D



C

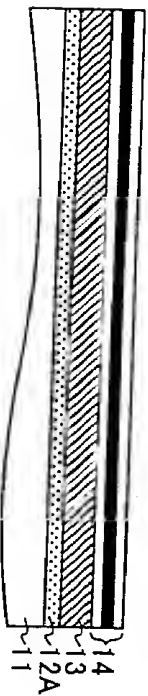
(RELATED ART)

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12/5/02



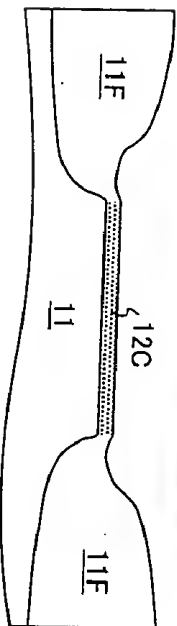


FIG. 11A



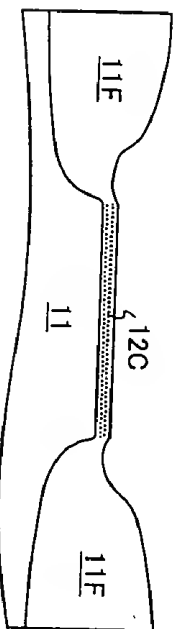
A

FIG. 11B



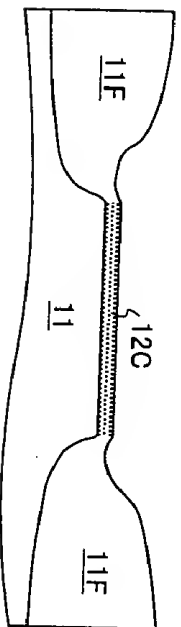
B

FIG. 11C



D

FIG. 11D



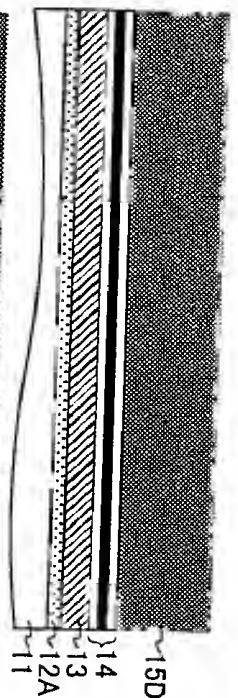
C

RELATED Art

Approved 10/15/02

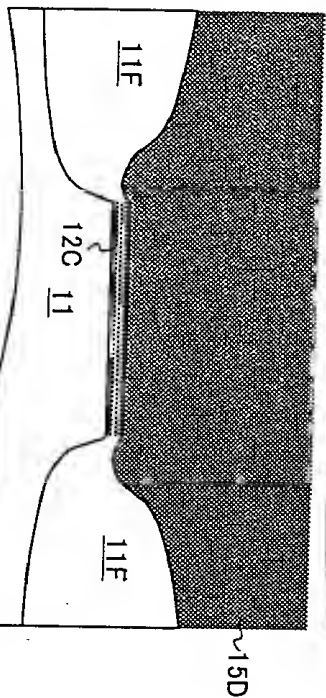
AP

FIG. 12A



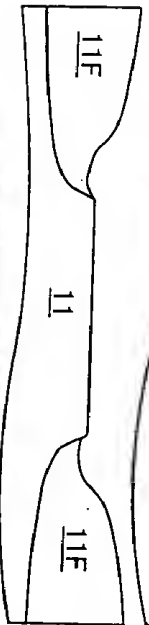
A

FIG. 12B



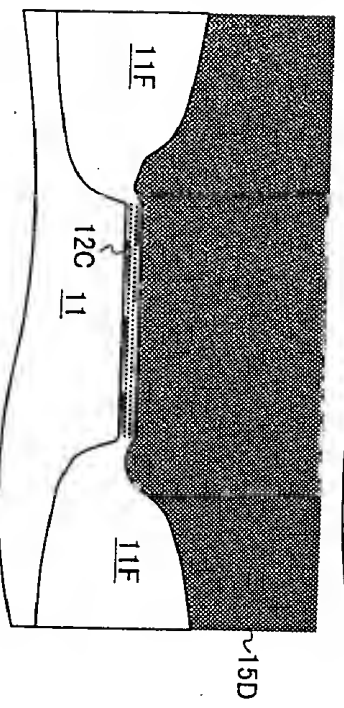
B

FIG. 12C



D

FIG. 12D



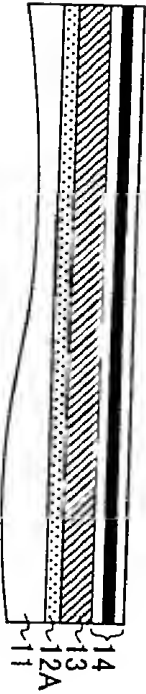
C



REJECTED (ACT)

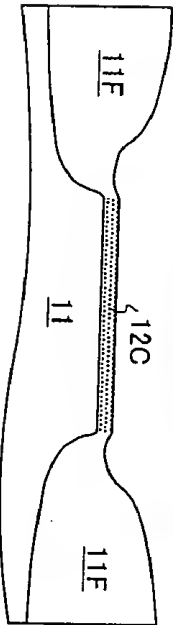
Alfred 12/5/02

FIG. 13A



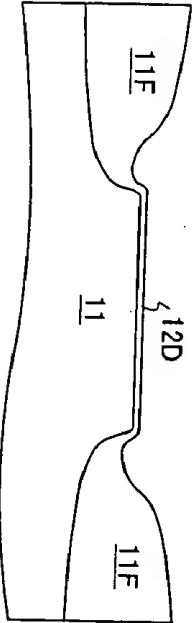
A

FIG. 13B



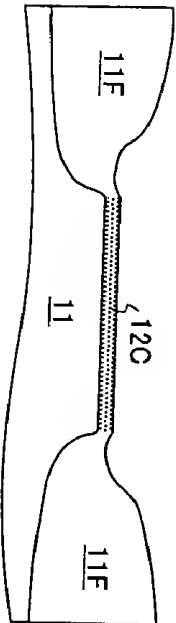
B

FIG. 13C



D

FIG. 13D



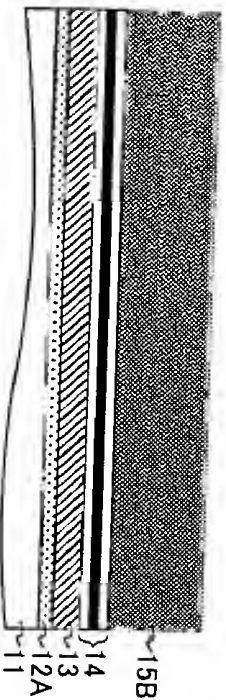
C



(RELATED ART)

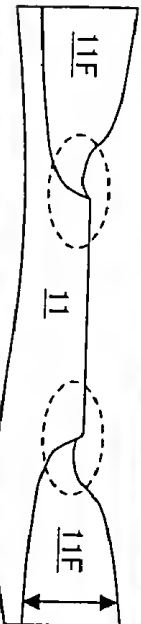
Approved 12/5/02

FIG. 14A



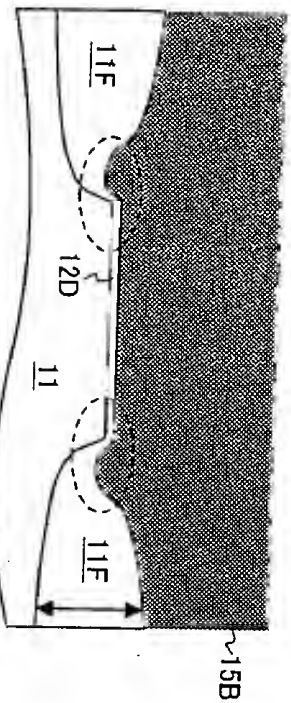
A

FIG. 14B



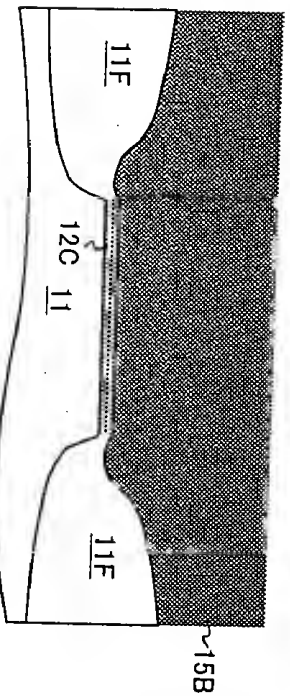
B

FIG. 14C



D

FIG. 14D



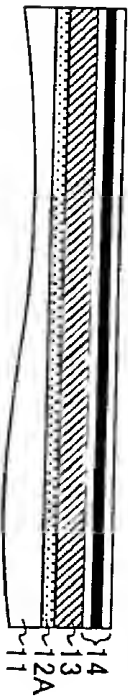
C



Related Art

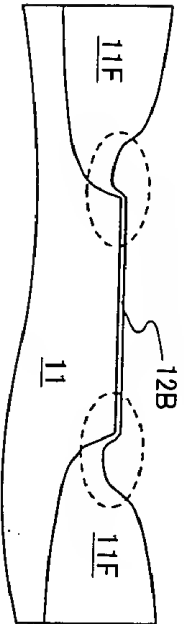
Approved 12/15/02

FIG. 15A



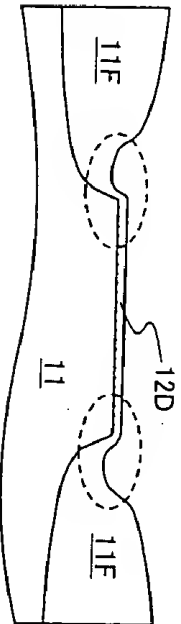
A

FIG. 15B



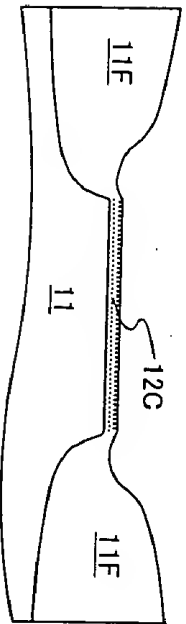
B

FIG. 15C



D

FIG. 15D



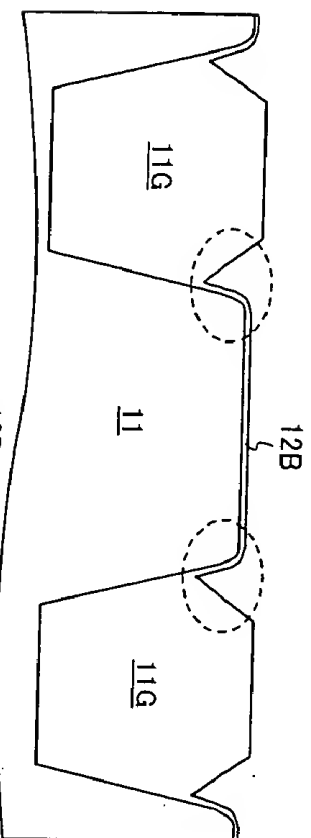
C



*Related Art*

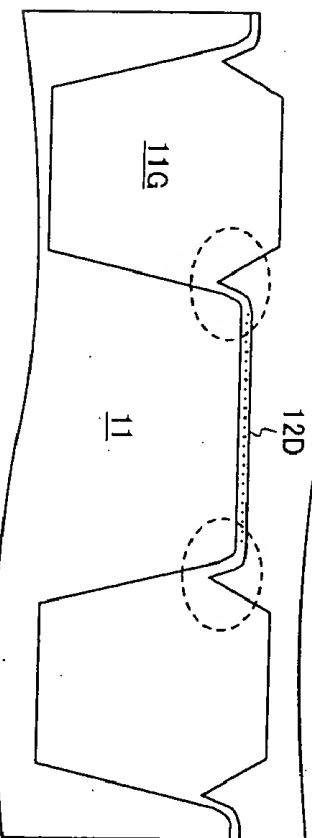
*Handwritten signature/initials*

FIG. 16A



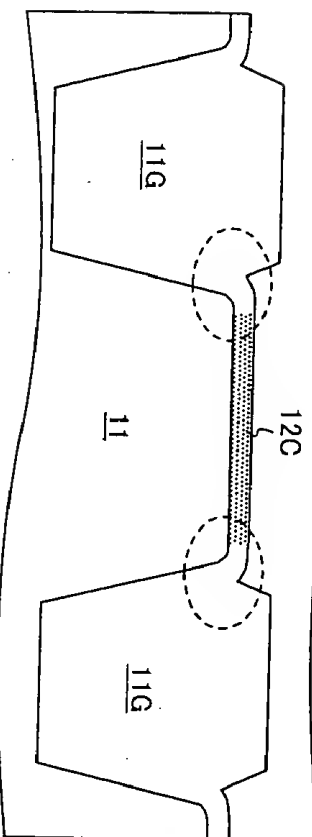
B

FIG. 16B



D

FIG. 16C



C

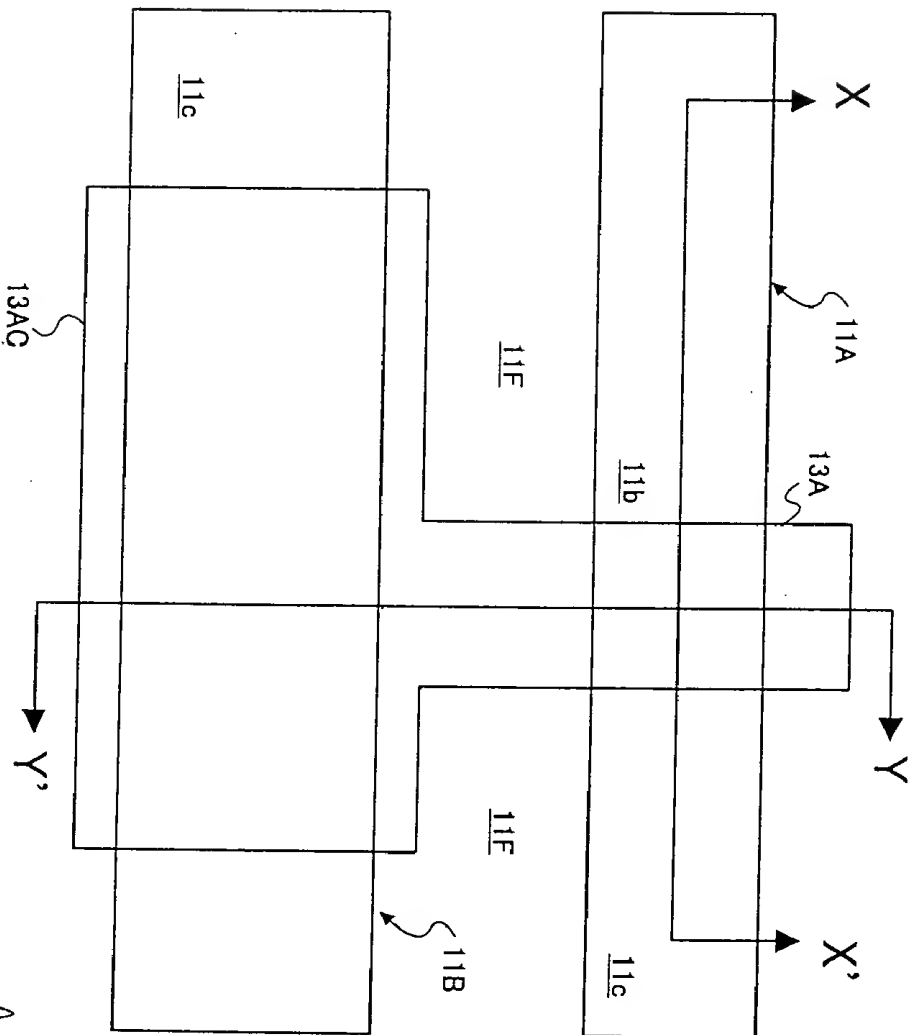


RETRACTED

Approved 12/5/02  
[Signature]



FIG. 17



(PRIOR ART)

Agreed 12/15/02  
#

FIG. 18A

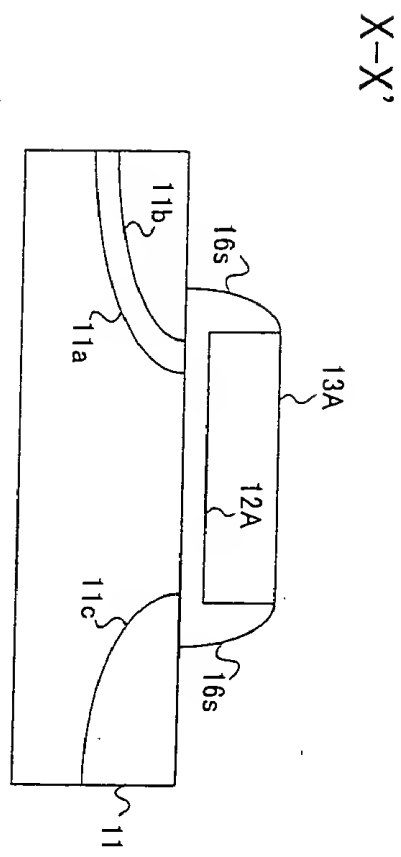
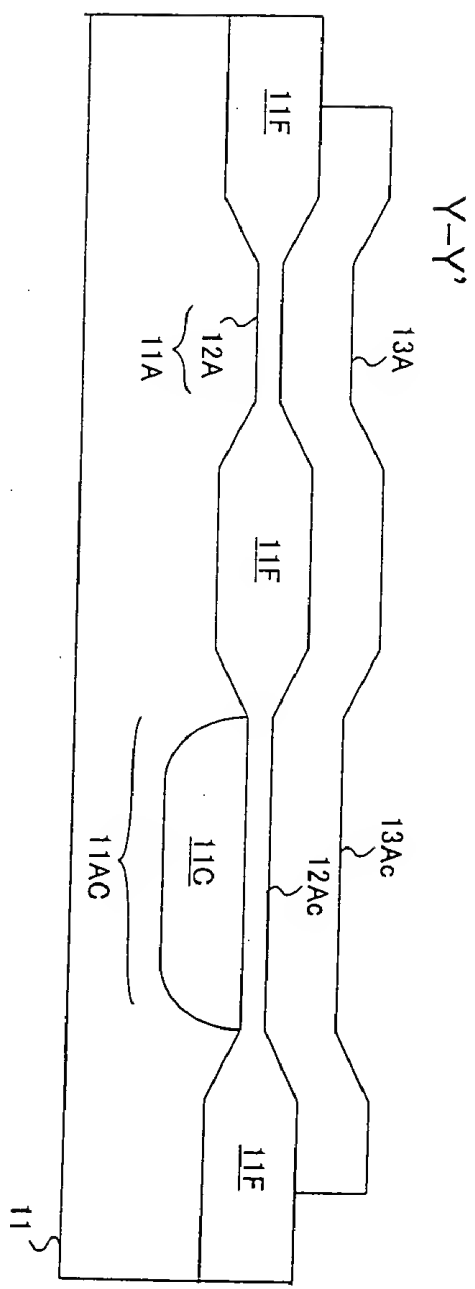


FIG. 18B



(PRIOR ART)

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 [Signature]



FIG. 19A

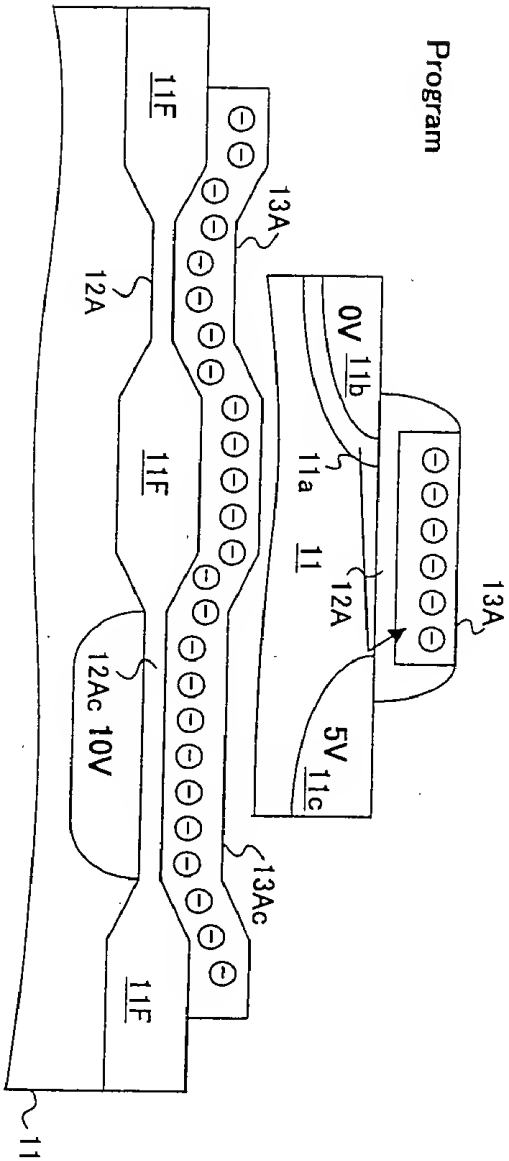


FIG. 19B

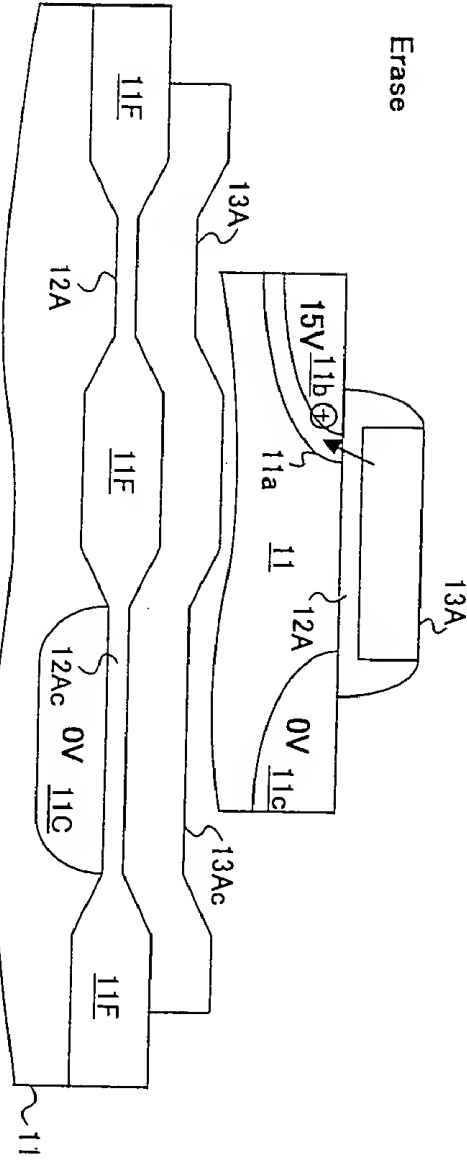


FIG. 19C

FIG. 19D

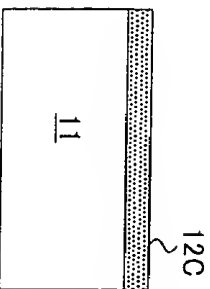


(PRIOR ART)

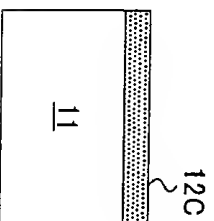
Applied 12/5/02



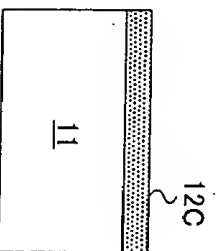
FIG. 20A



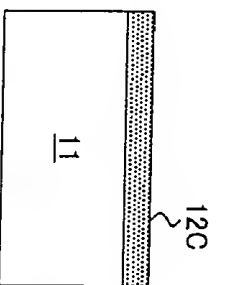
A



B

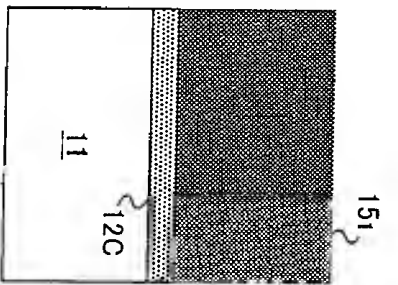
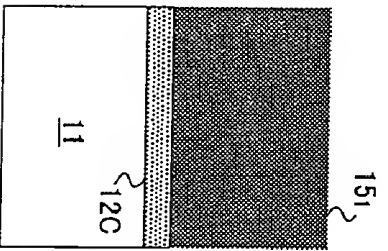
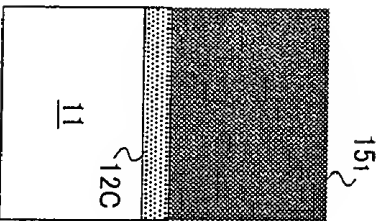
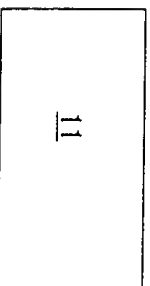


D



C

FIG. 20B



(PRIOR ART)

Approved 12/5/02



FIG. 20C

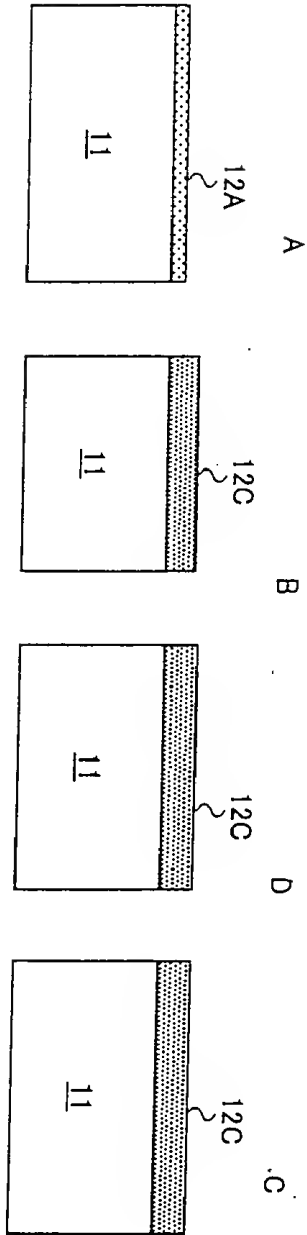
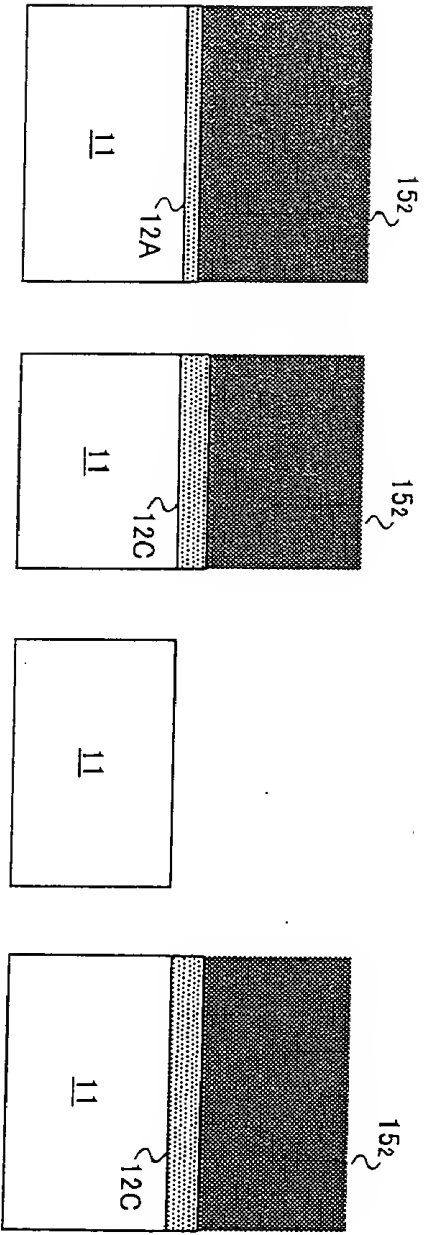


FIG. 20D



(PRIOR ART)

Hybrid w/100



FIG. 20E

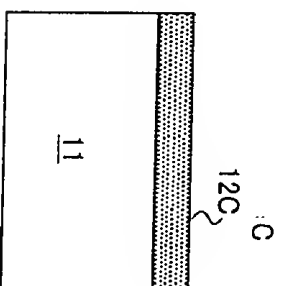
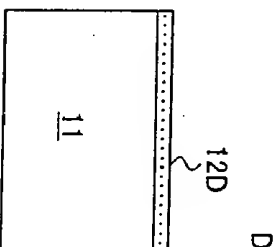
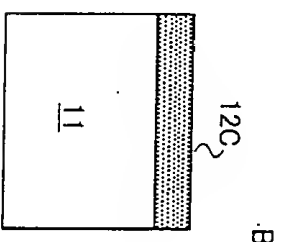
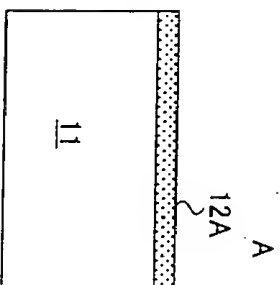
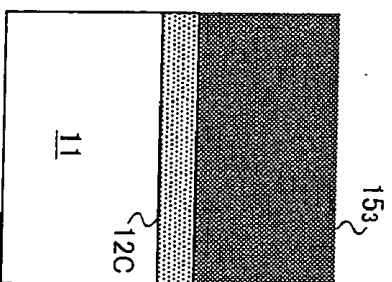
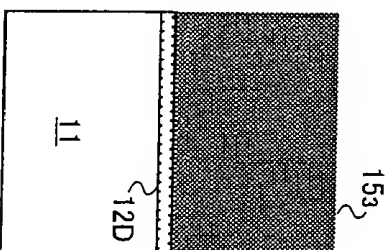
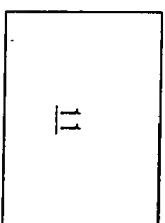
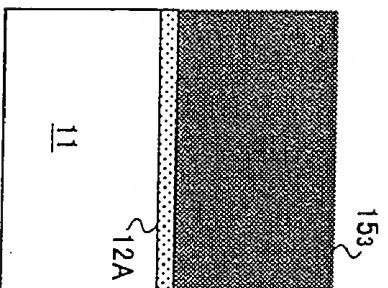


FIG. 20F



(Prior Art)

Appl 11/511111



FIG. 20G

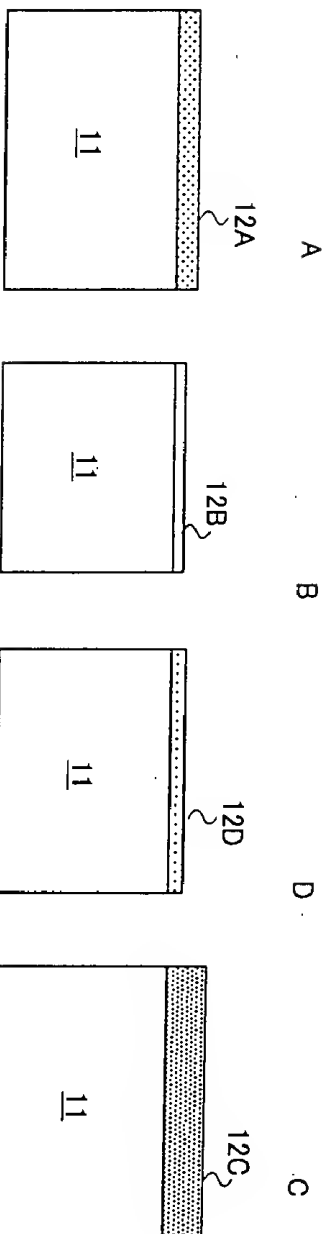
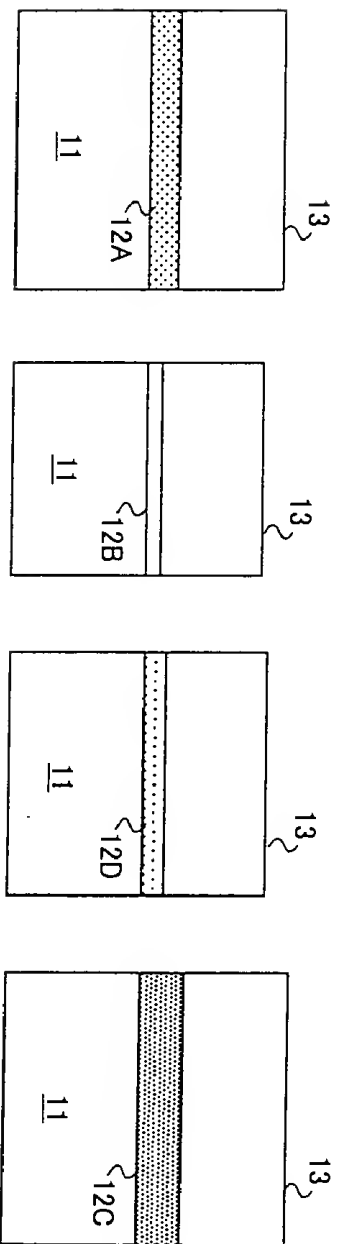


FIG. 20H

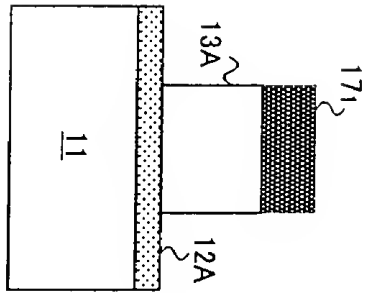


(PRIOR ART)

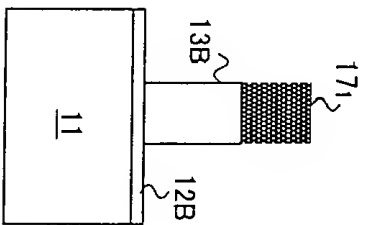
12/5/02



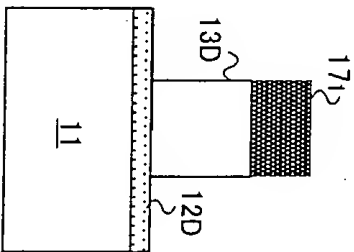
FIG. 20I



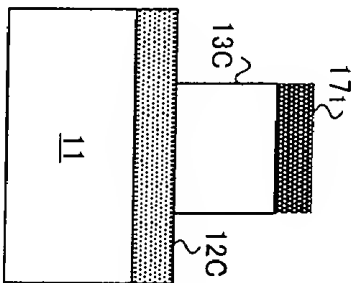
A



B

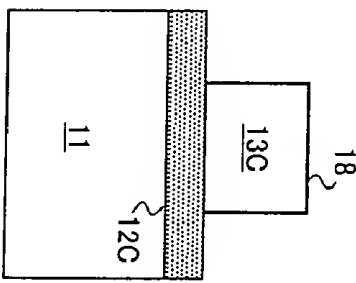
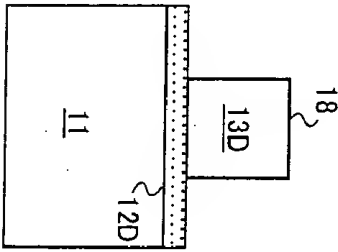
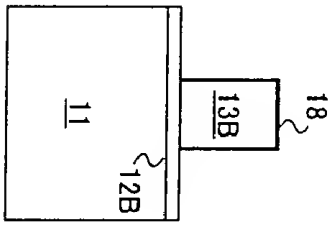
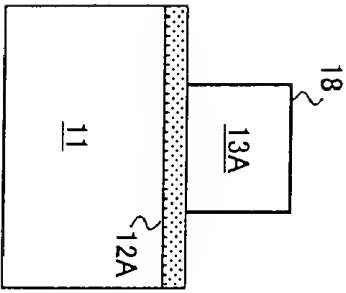


D



C

FIG. 20J



(Prior Art)

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*[Signature]*



FIG. 20K

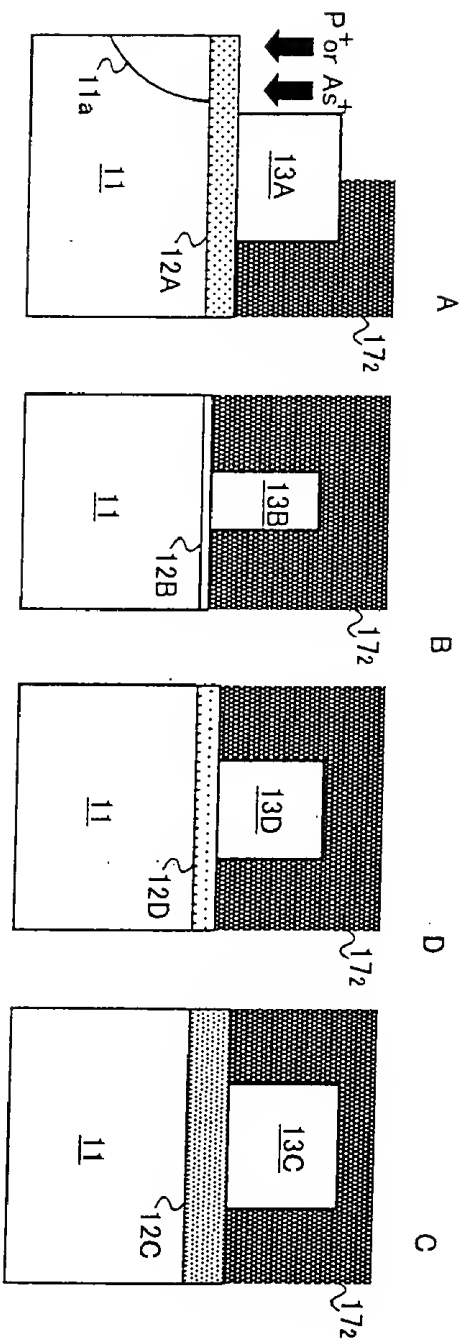
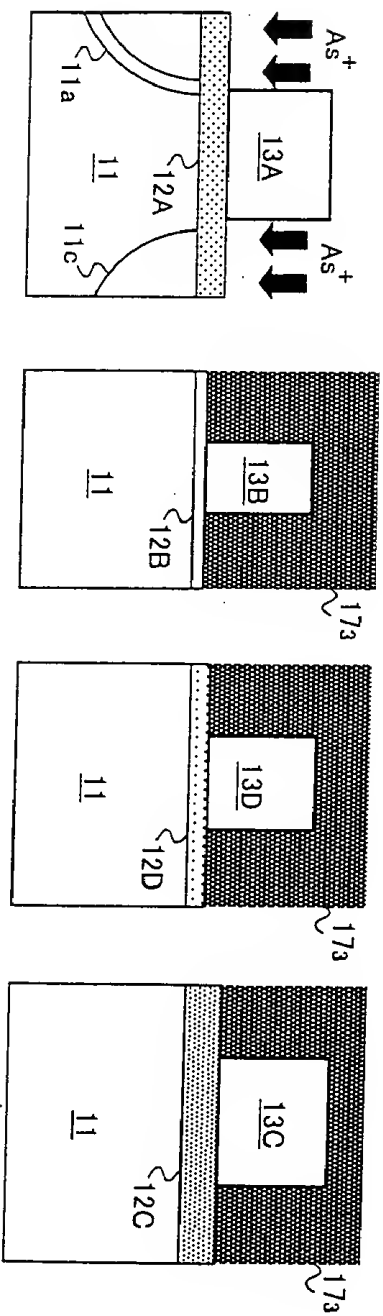


FIG. 20L



(PRIOR ART)

Approved 12/5/02



FIG. 20N

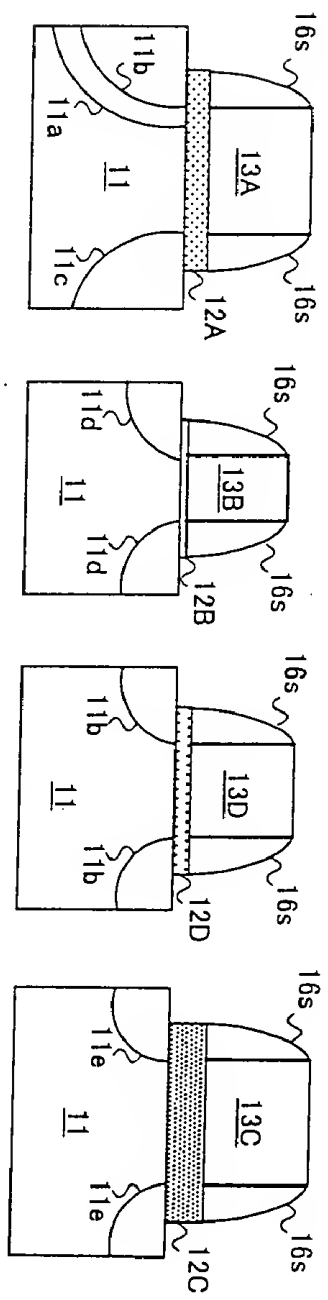
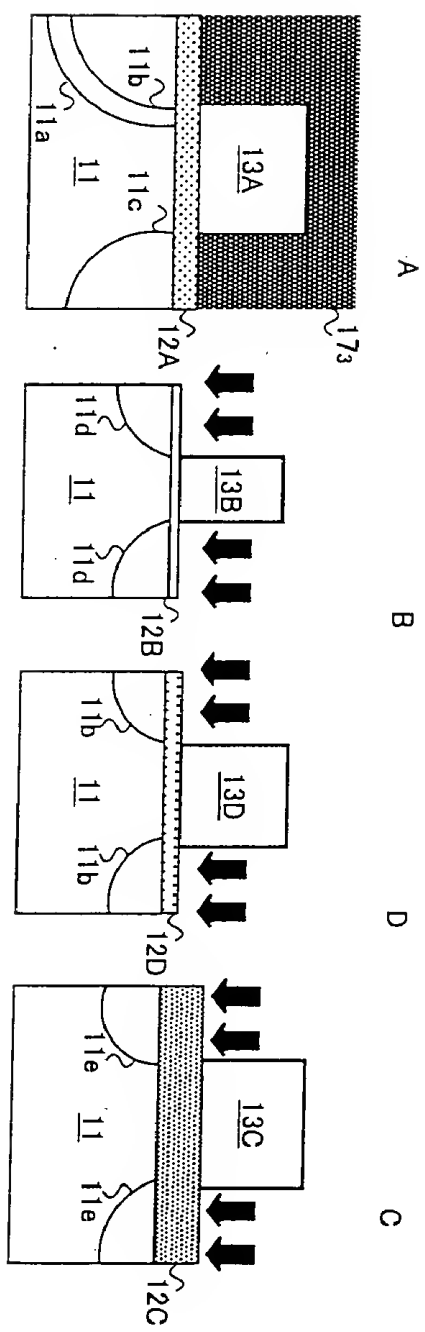


FIG. 20M



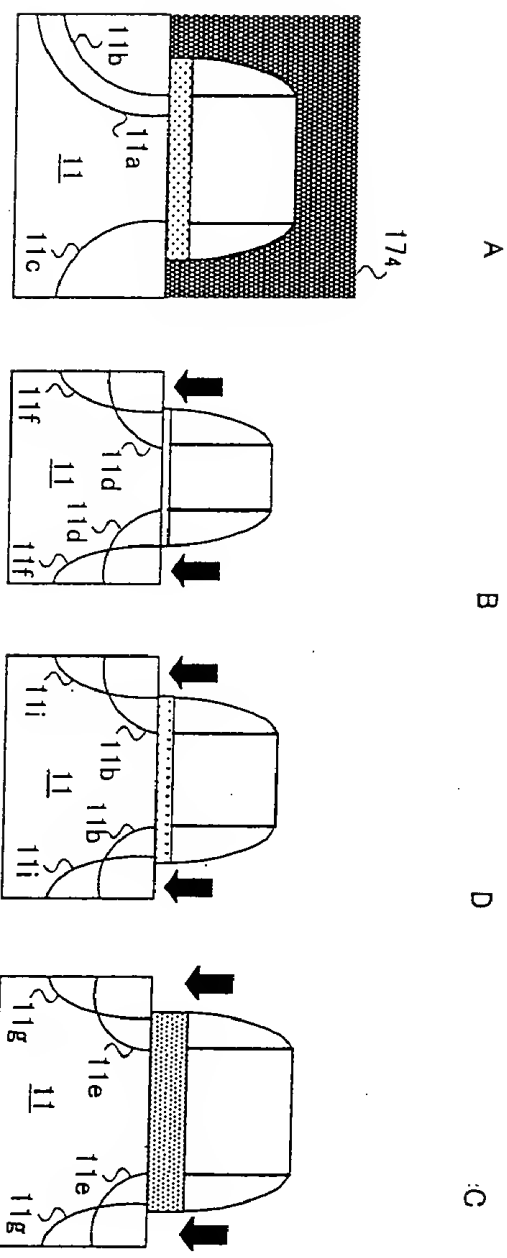
(Prior Art)

Appnd w/5/02





FIG. 200

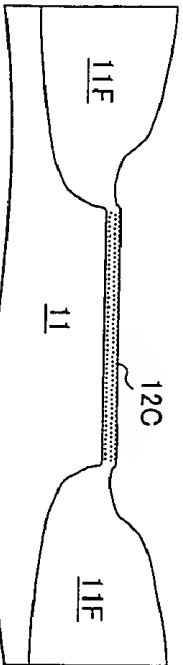


(PRIOR ART)

*Approved 12/15/02*

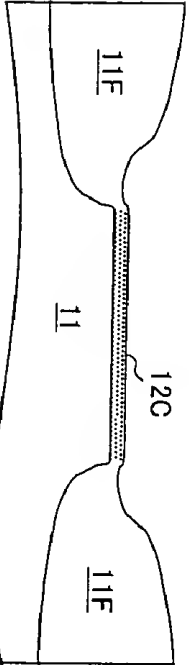
*[Signature]*

FIG. 21A



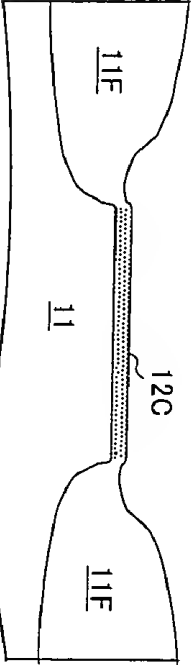
A

FIG. 21B



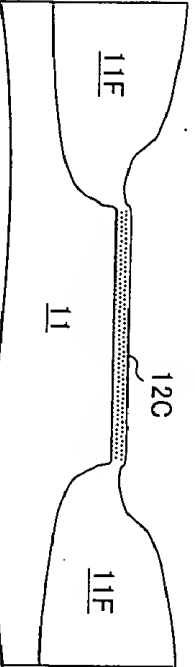
B

FIG. 21C



D

FIG. 21D



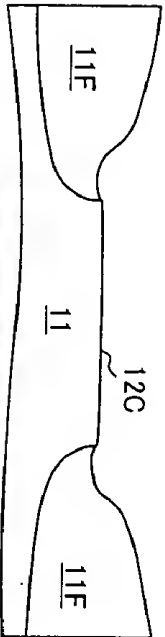
C



(RETRACTED ACT)

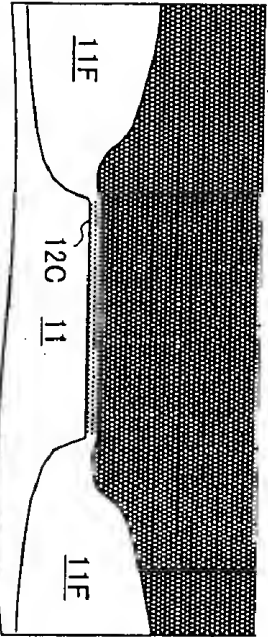
Appendix  
12/5/22

FIG. 22A



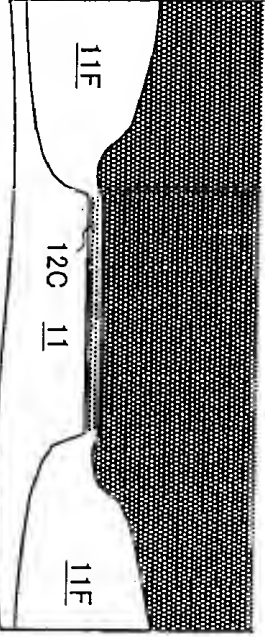
A

FIG. 22B



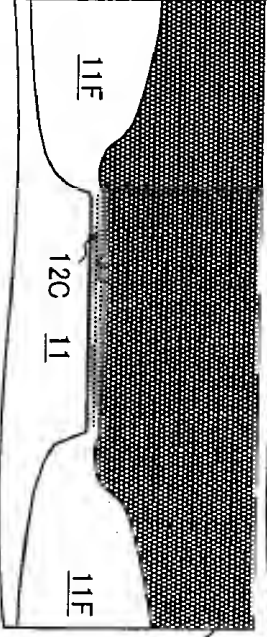
B

FIG. 22C



D

FIG. 22D



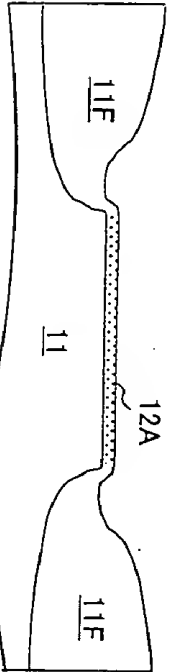
C



RELATED ART

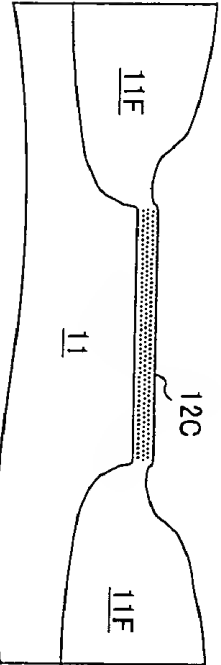
Approved 12/15/02

FIG. 23A



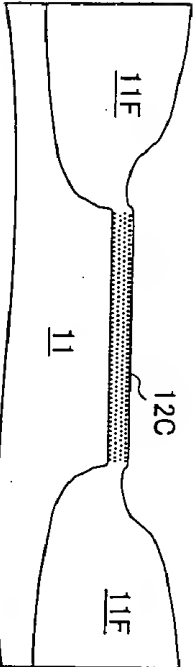
A

FIG. 23B



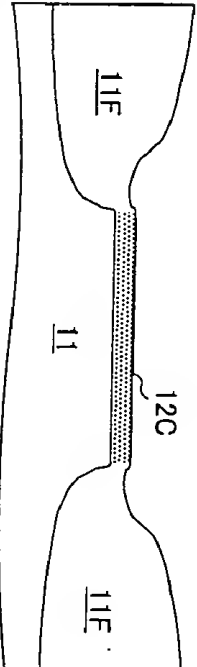
B

FIG. 23C



D

FIG. 23D



C

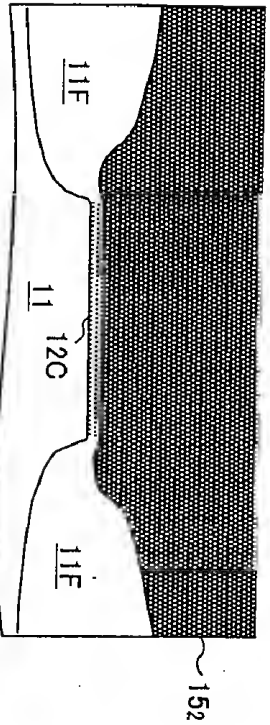


*Related Art*

*Approved Off*  
*11/15/02*

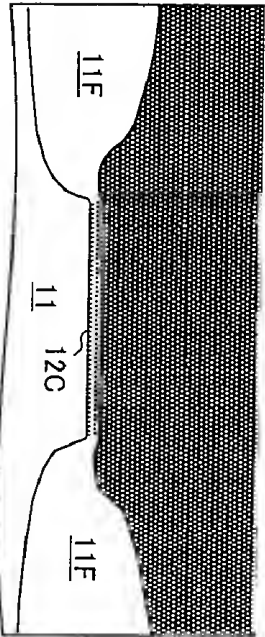


FIG. 24A



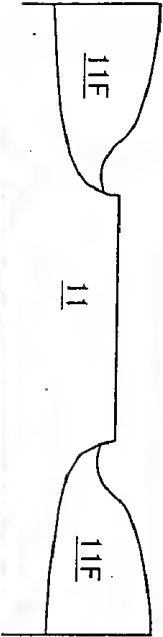
A

FIG. 24B



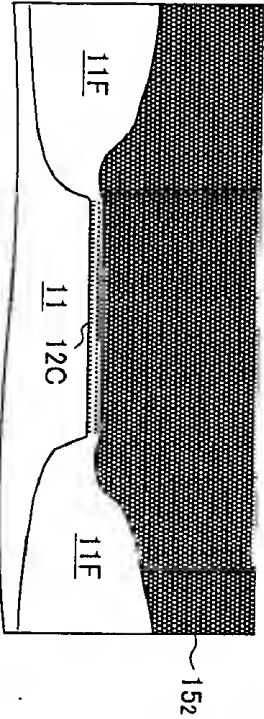
B

FIG. 24C



C

FIG. 24D

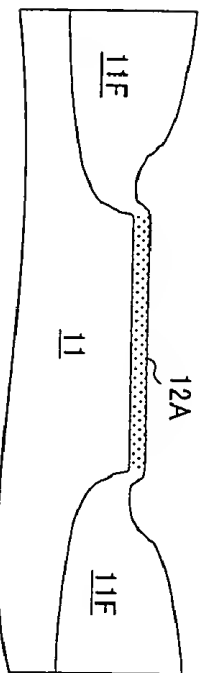


D

RELATED ART

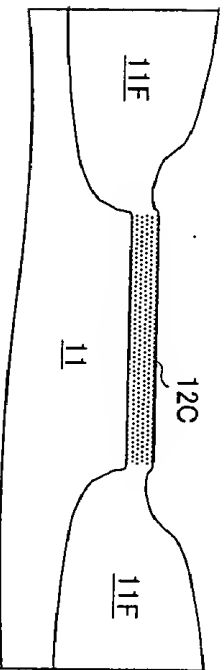
Appendix

FIG. 25A



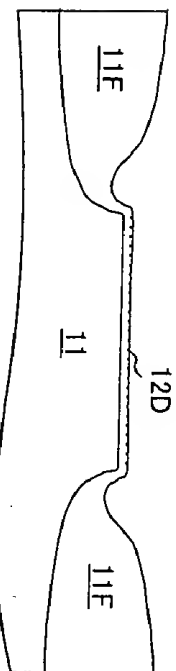
A

FIG. 25B



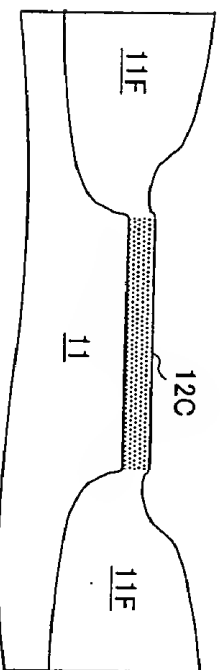
B

FIG. 25C



D

FIG. 25D



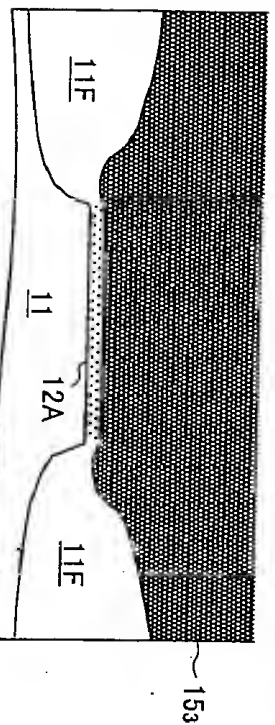
C



*RELATED Art*

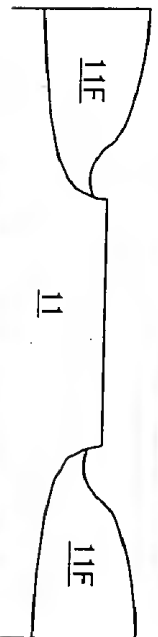
*Approved 12/5/02*

FIG. 26A



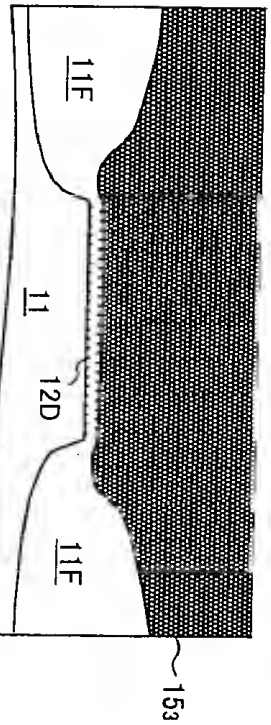
A

FIG. 26B



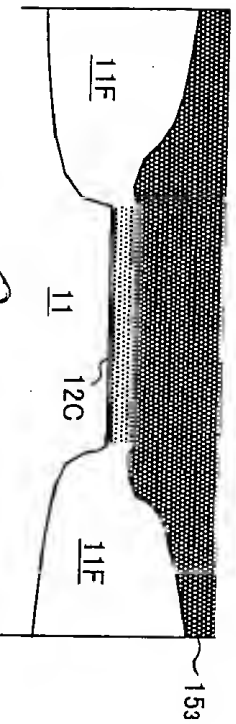
B

FIG. 26C



D

FIG. 26D



C



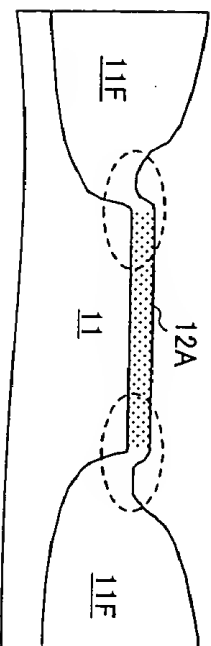
RELATED ART

April 14/5/02

A handwritten signature, possibly "J. H. H.", written in ink.

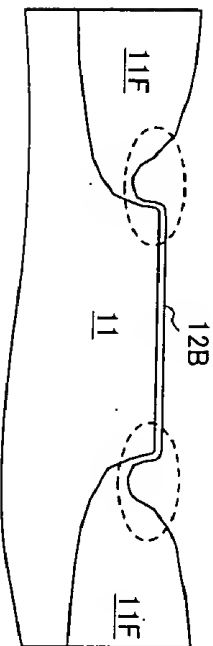


FIG. 27A



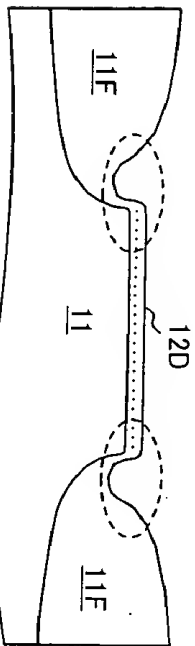
A

FIG. 27B



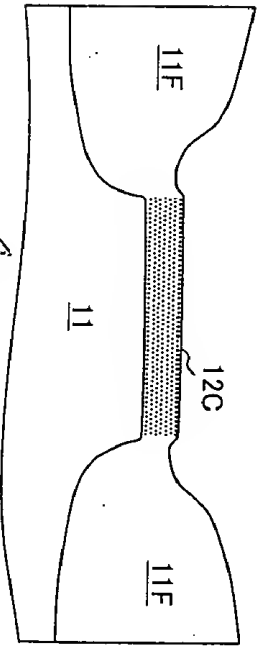
B

FIG. 27C



D

FIG. 27D



C

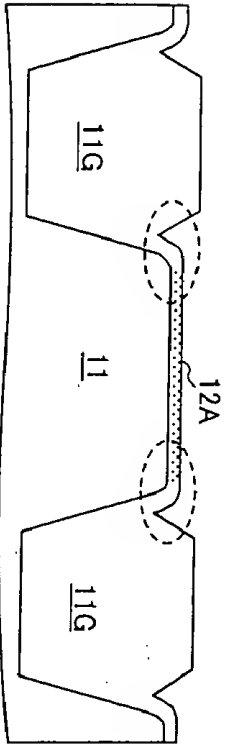
(RELATED ART)

Approved 12/5/02



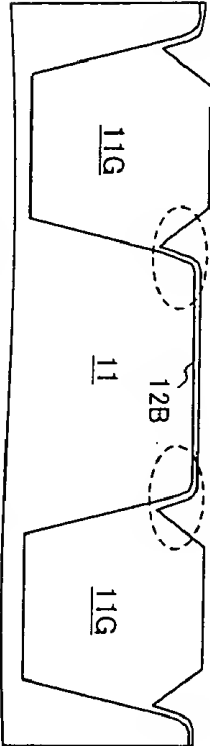


FIG. 28A



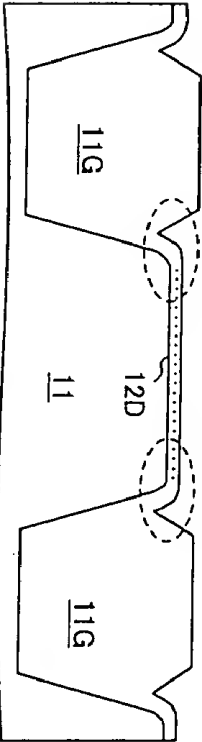
A

FIG. 28B



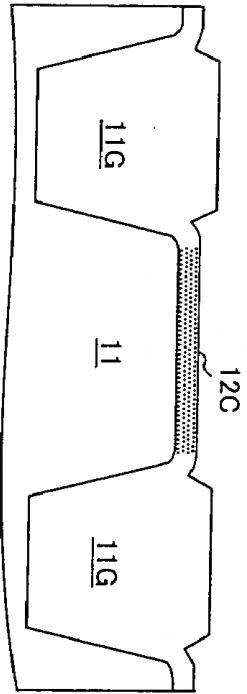
B

FIG. 28C



D

FIG. 28D



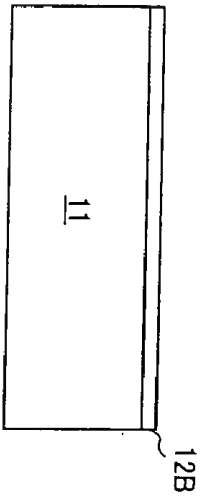
C

RELATED

Art

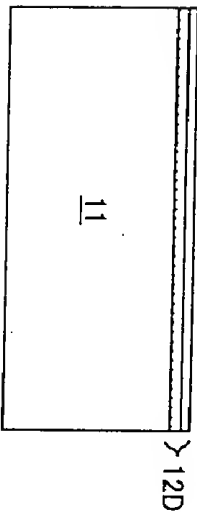
April 12/5/02

FIG. 29A



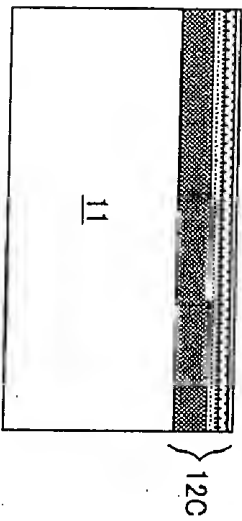
B

FIG. 29B



D

FIG. 29C



C

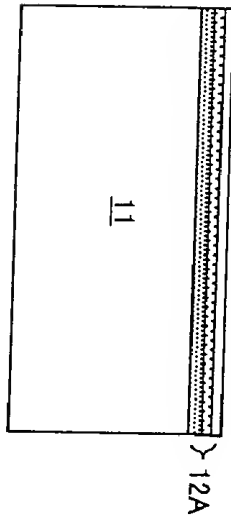


*Related Art*

*April 12/5/02*

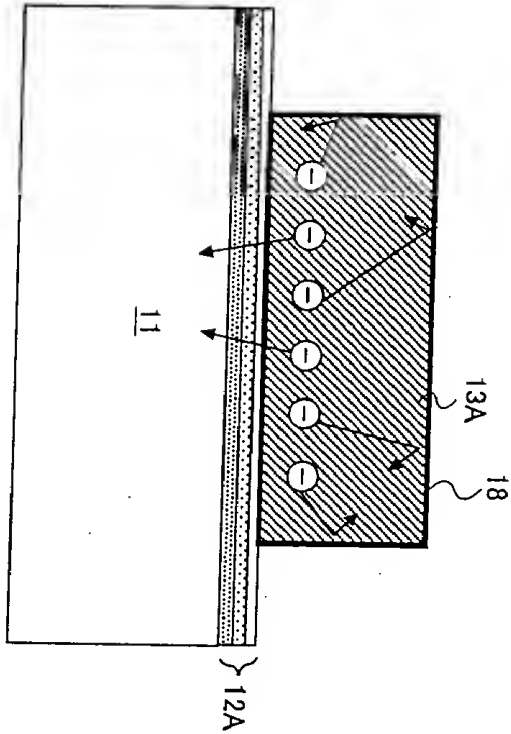


FIG. 30A



A

FIG. 30B



(RELATED ART)

Amend 2/5/02